

X-Ray Laue Diffraction Microscopy

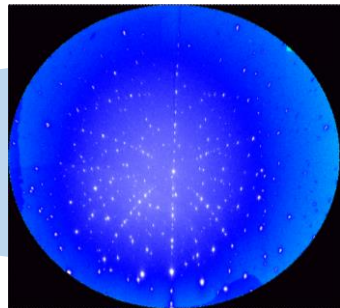
Nano- and microscale X-ray characterisation of functional materials and microstructure

J.S. Micha, O. Robach, S. Tardif, O. Ulrich, R.R.P. Purushottam Raj Purohit, O. Geaymond, L. Martinelli, G. Renaud, B. Formet, M. De Santis, X. Biquard, Anaël Coste, D. Mornex

Univ. Grenoble Alpes, CEA/IRIG/MEM & SyMMES, CNRS Institut Néel, CNRS SERAS



CRG-IF BM32 beamline @ ESRF



Single crystal Laue Pattern



2D map:
Orientation
dev. strain map

Complex materials
Polycrystals, defects

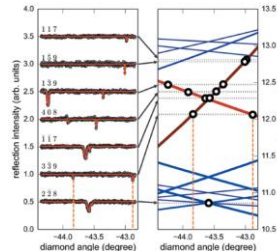
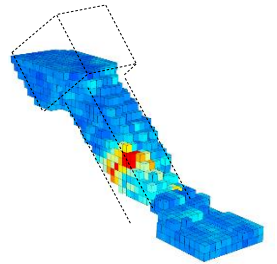
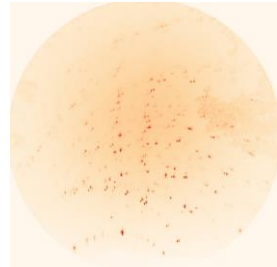
3D map

Full tensor
stress/strain

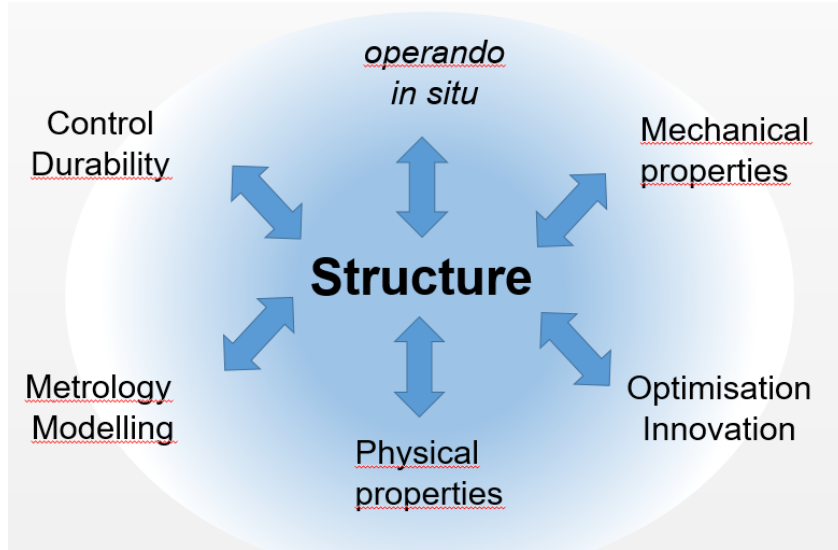
AI-based Indexing

Depth resolution

Energy resolution



Objectives & scopes



For

Materials science, Nanoscience
Real and model systems
Microstructure, nano- and microobjects, microdevices
Fundamental science & technology-related materials

Needs

Accurate, quantitative experimental data
Accessible measurements
Transversal technique (metals, oxide, semiconductors,...)
Complementary with SEM, TEM



BM32
beamline

- ✓ **Dedicated station**
- ✓ **Unique in Europe**
- ✓ **Home-dev. software (AI)**

@



Laue Microscopy

Local lattice parameters, strain, orientation, microstructure

HR spatial: 300 nm x 300 nm
HR angular: $0,006^\circ \Leftrightarrow 0,01\%$

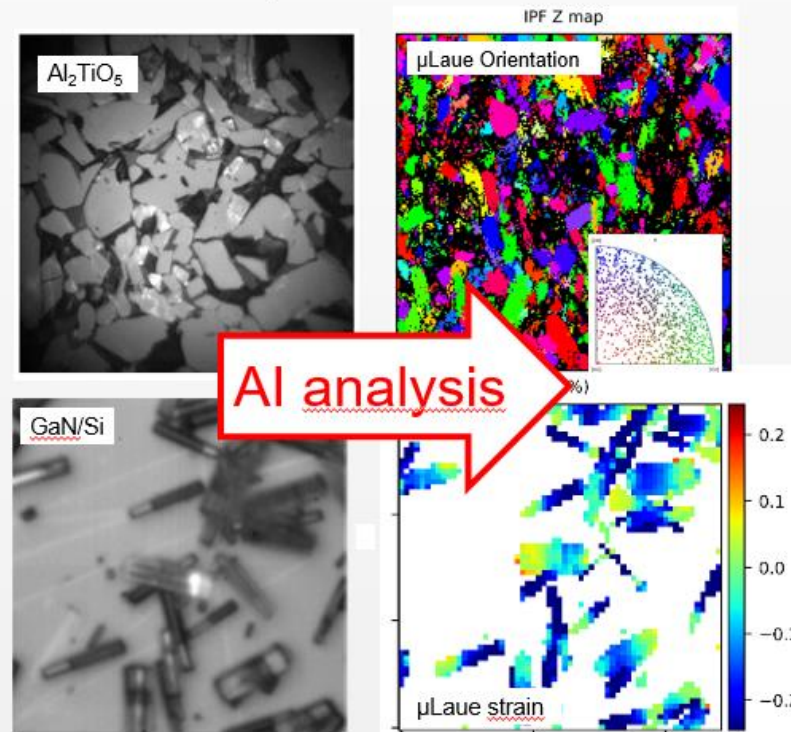
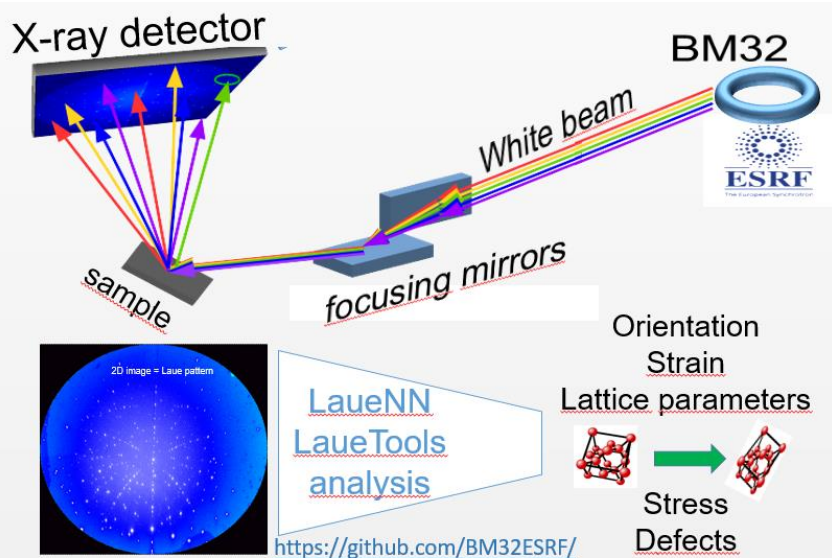
Capabilities

No sample preparation
In situ & operando (T, force, I, V, XEOL,...)

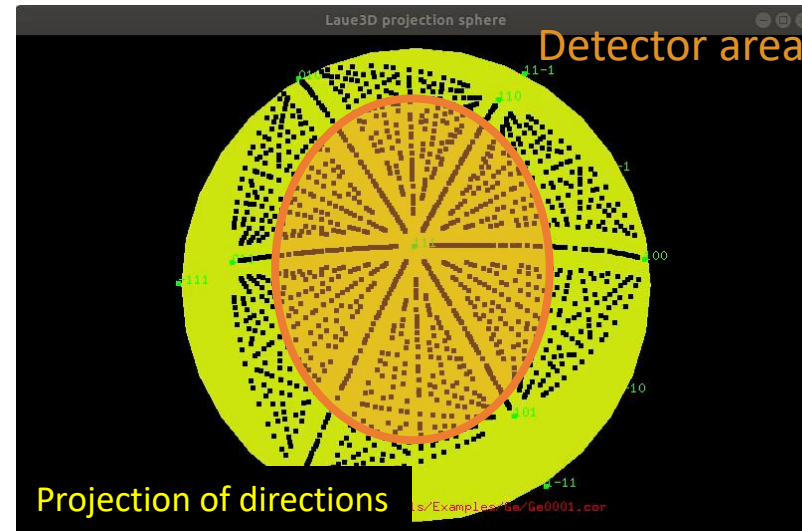
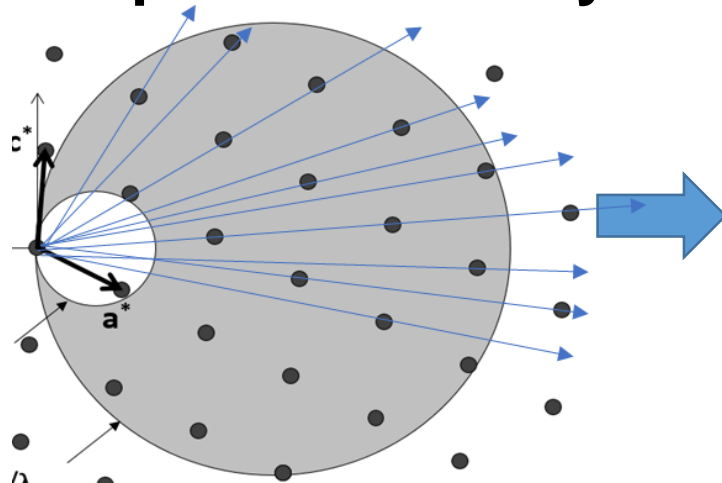
Polycrystalline & single crystal
2D mapping (9000 pts/h) Flexible FOV
Damaged material

Augmented μ Laue

Depth resolution (500nm)
Stress assessment
Extended defects (plasticity)

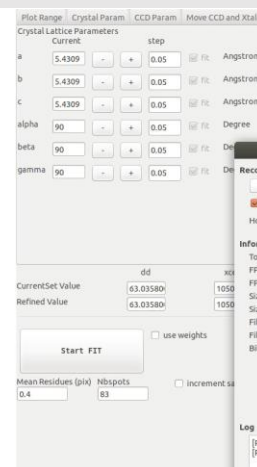
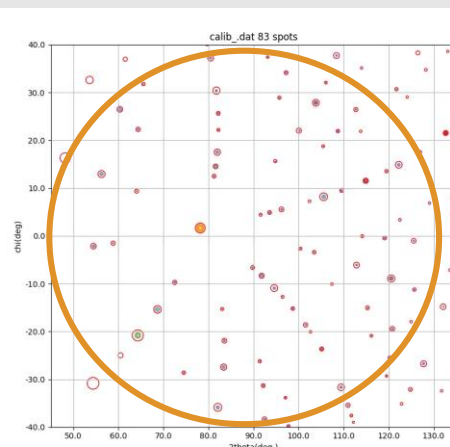
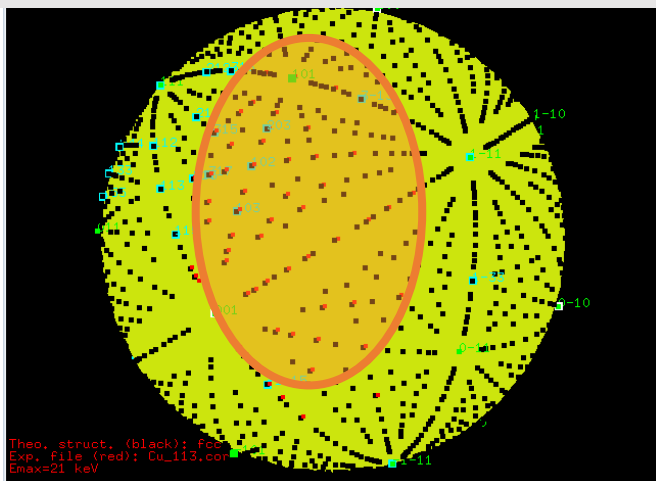


Principles: sensitivity & resolution



Absolute positions => **orientation**

Relative positions / reference => **strain**



Effect of strain or lattice parameters change

Standard Laue diffraction

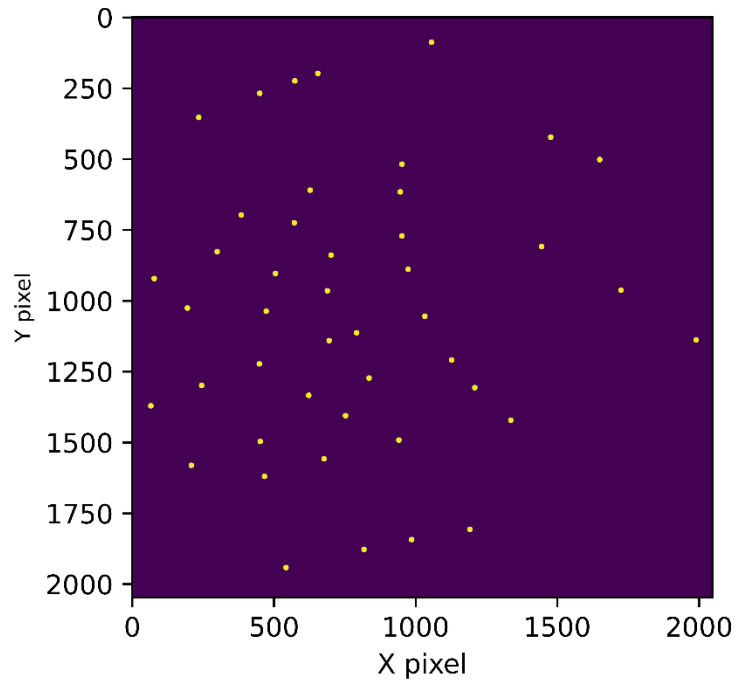
Experimental & quantitative determination of unit cell :

- Orientation
- (angular) Shape (lattice parameters, strain)

- **Absolute** values
- **10⁻⁴ resolution** for
 - high absorbing material
 - low defects density
- **Better resolution on gradients**

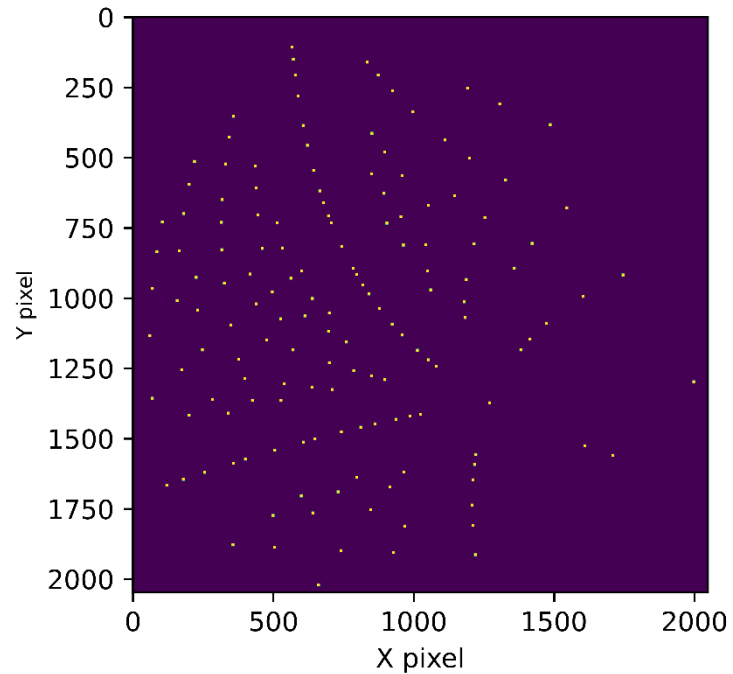
AI-based Laue pattern indexing: complexity

Simulated “complete” Laue pattern
Single crystal Cu
(cubic)



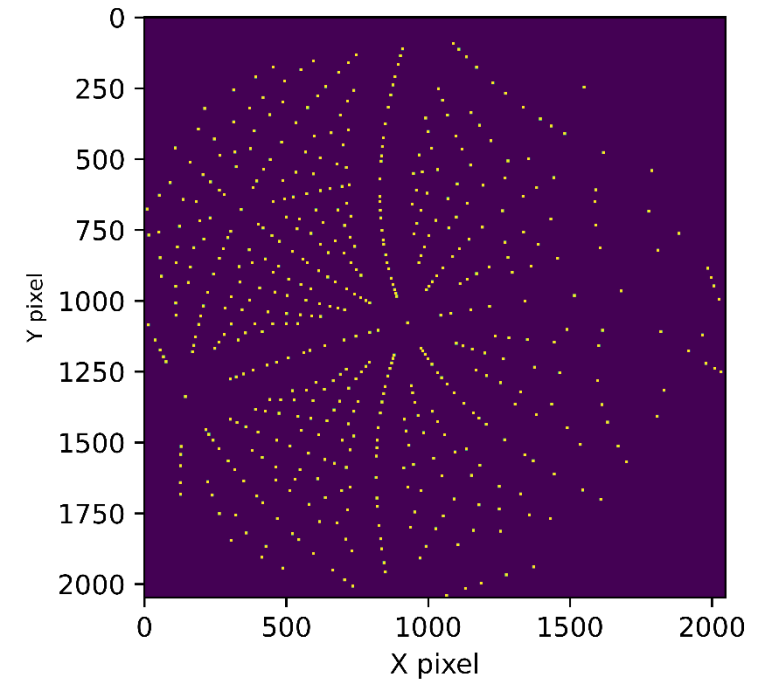
Nb. of spots in detector: ~40

Simulated “complete” Laue pattern
Single crystal UO₂
(Large cubic unit cell)



Nb. of spots in detector: ~160

Simulated “complete” Laue pattern
Single crystal ZrO₂
(monoclinic)

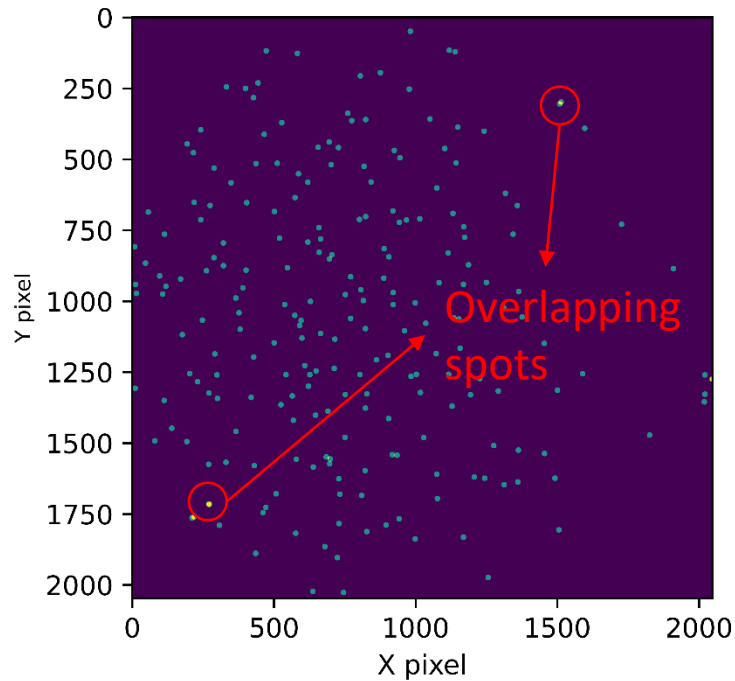


Nb. of spots in detector: ~500

*Detector at 70mm from the sample surface

AI-based Laue pattern indexing: complexity

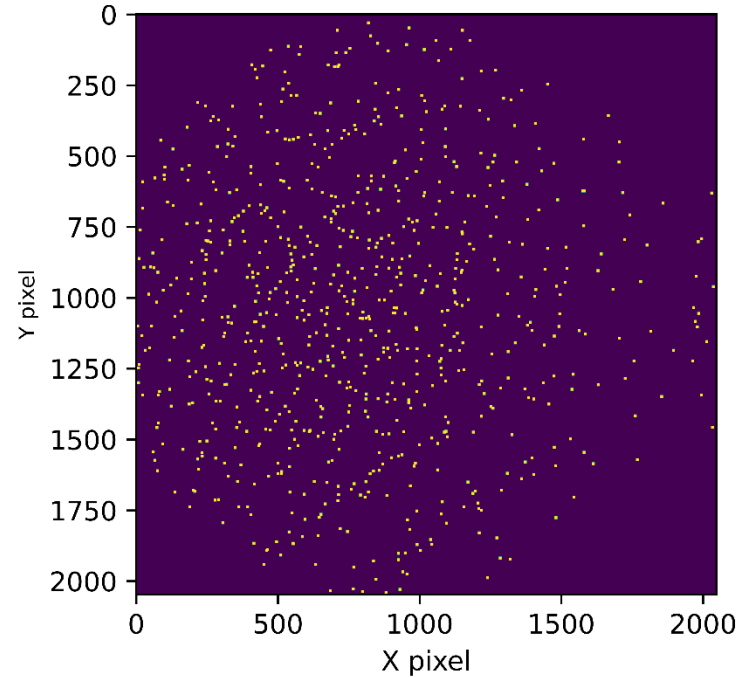
Simulated “complete” Laue pattern
Polycrystalline Cu (5 grains)
(cubic)



Nb. of spots in detector: ~230

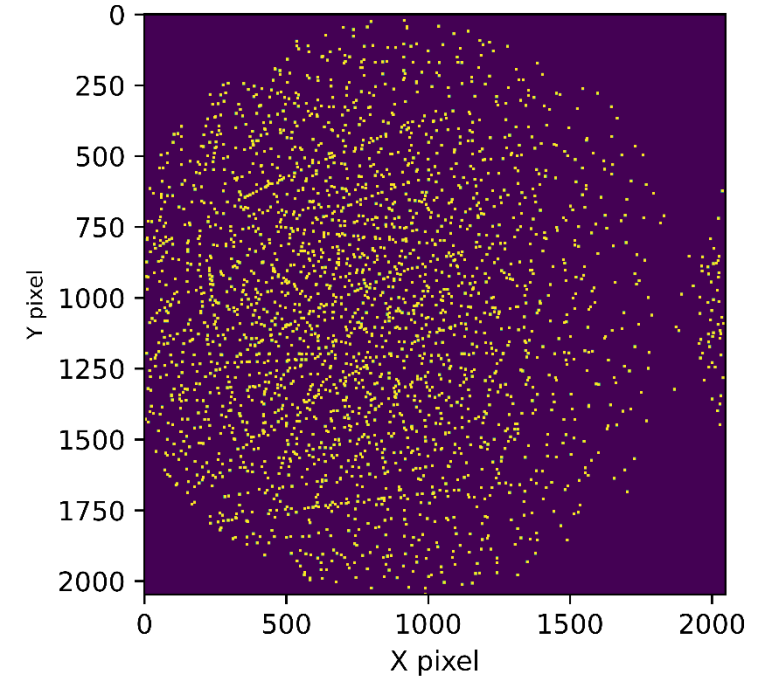
- In reality, we also have photon noise/ dead pixels/ saturated peaks on the detector (also detector efficiency)
- Also the intensity of Laue spots for grains diffracting underneath the surface grains will not be the same

Simulated “complete” Laue pattern
Polycrystalline UO₂ (5 grains)
(Large cubic unit cell)



Nb. of spots in detector: ~800

Simulated “complete” Laue pattern
Polycrystalline ZrO₂ (5 grains)
(monoclinic)



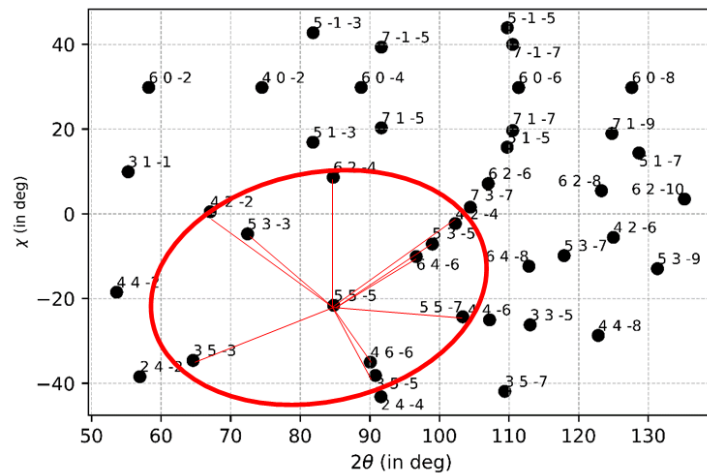
Nb. of spots in detector: ~2600

AI-based Laue pattern indexing: extracting Laue features for training

Ability of the neural network learning depends strongly on the applicability of the feature it is dealt with.

Angular space is more meaningful in Laue

Simulated Laue Pattern for single crystal Cu

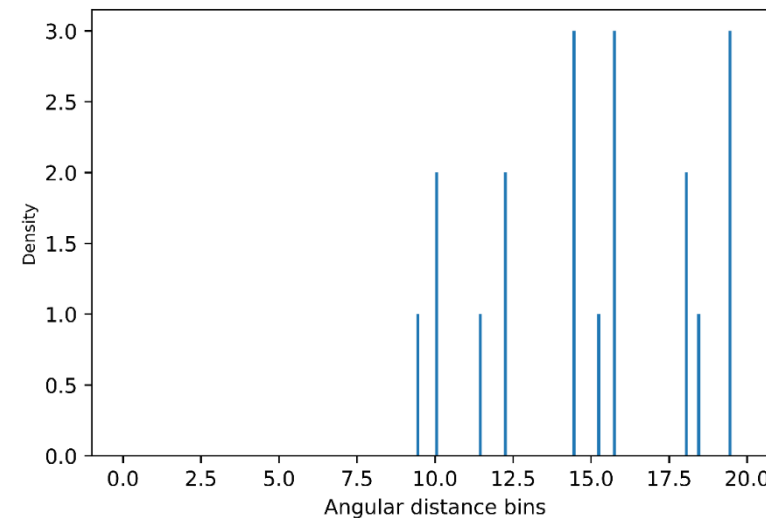


Binning of angular distance between neighbor spots



Neighbors defined by limit search angle (here 20°)

Angular distribution for (55-5)

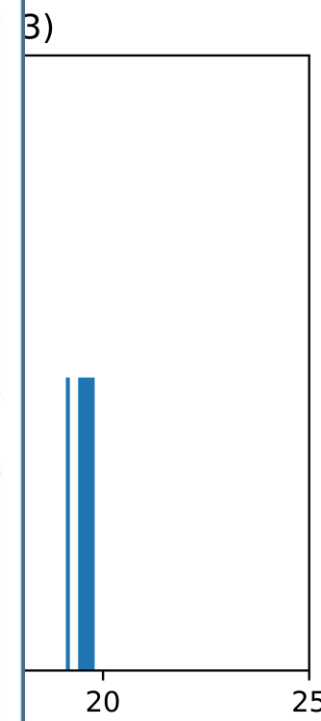
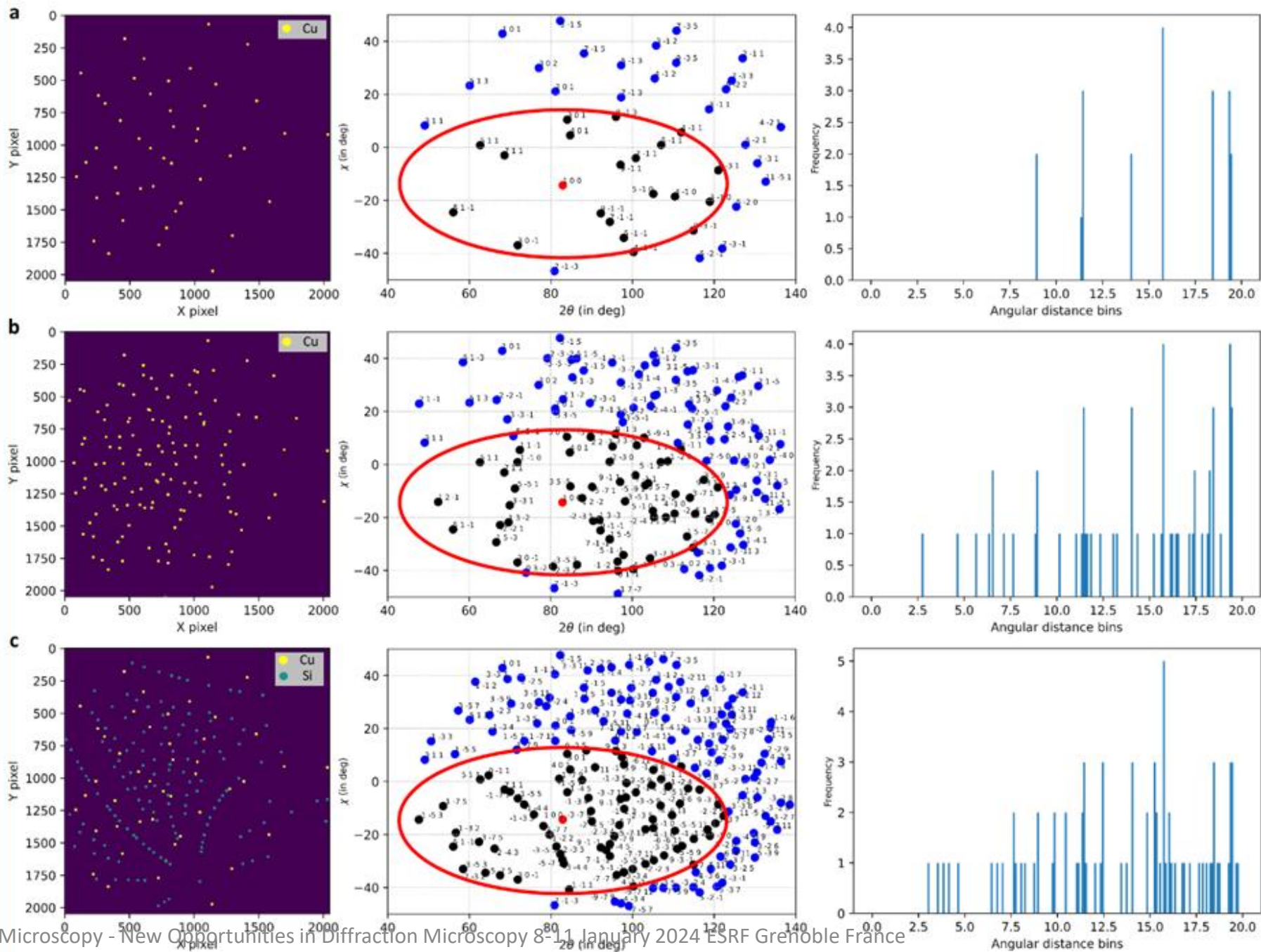
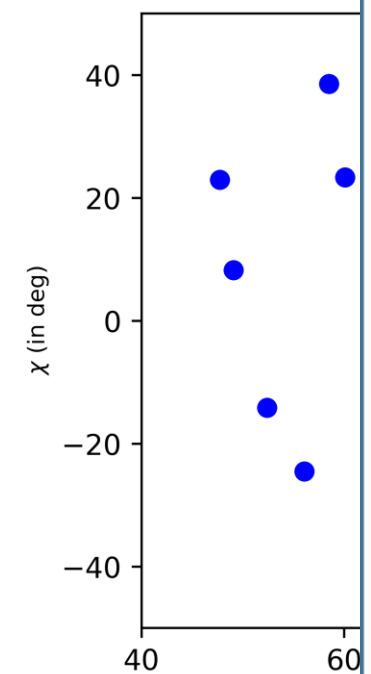


→ Angular distance distribution is used as input for the Neural network.

AI-based Laue

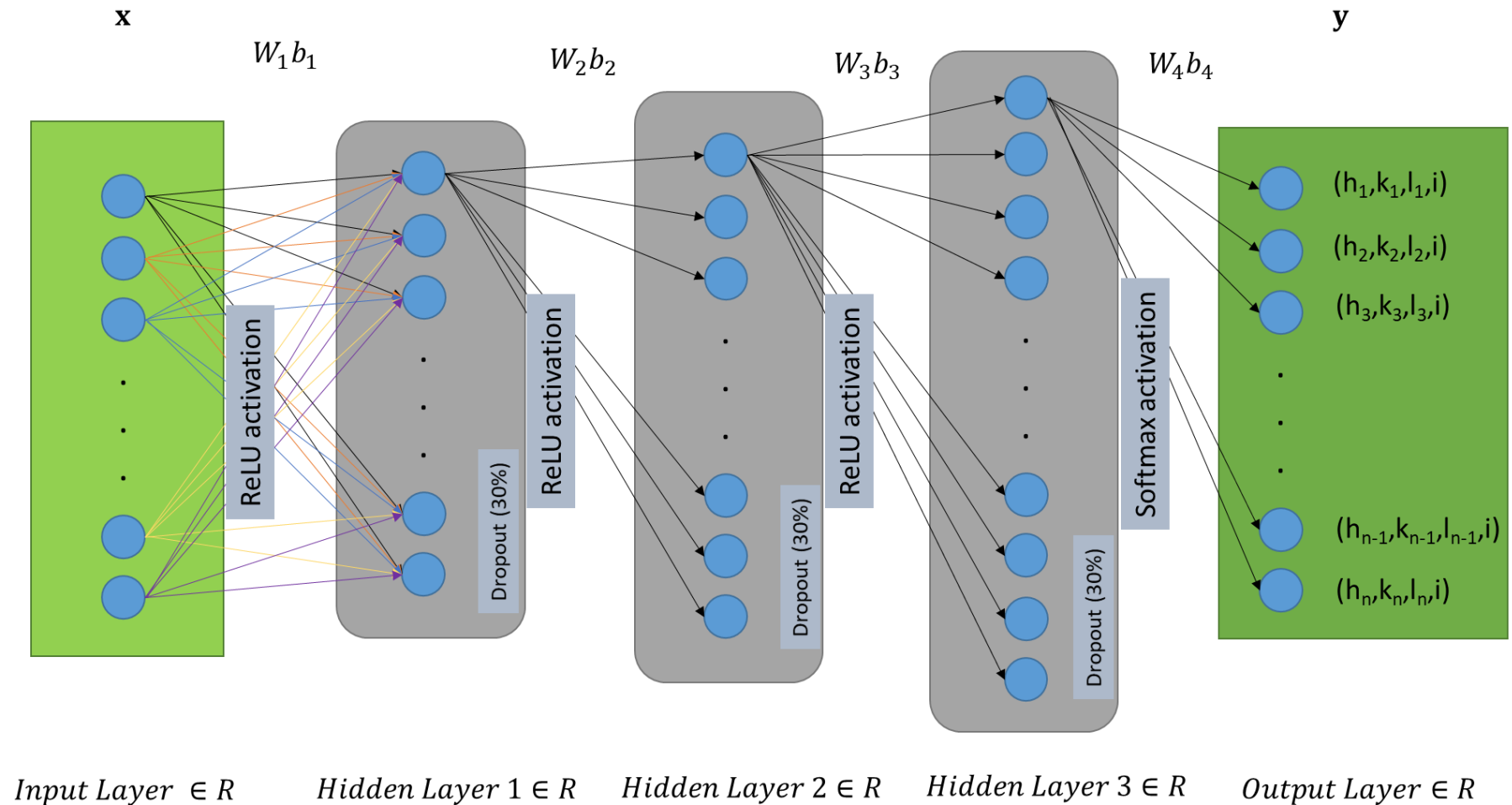
Ability of the neu

Angular space i



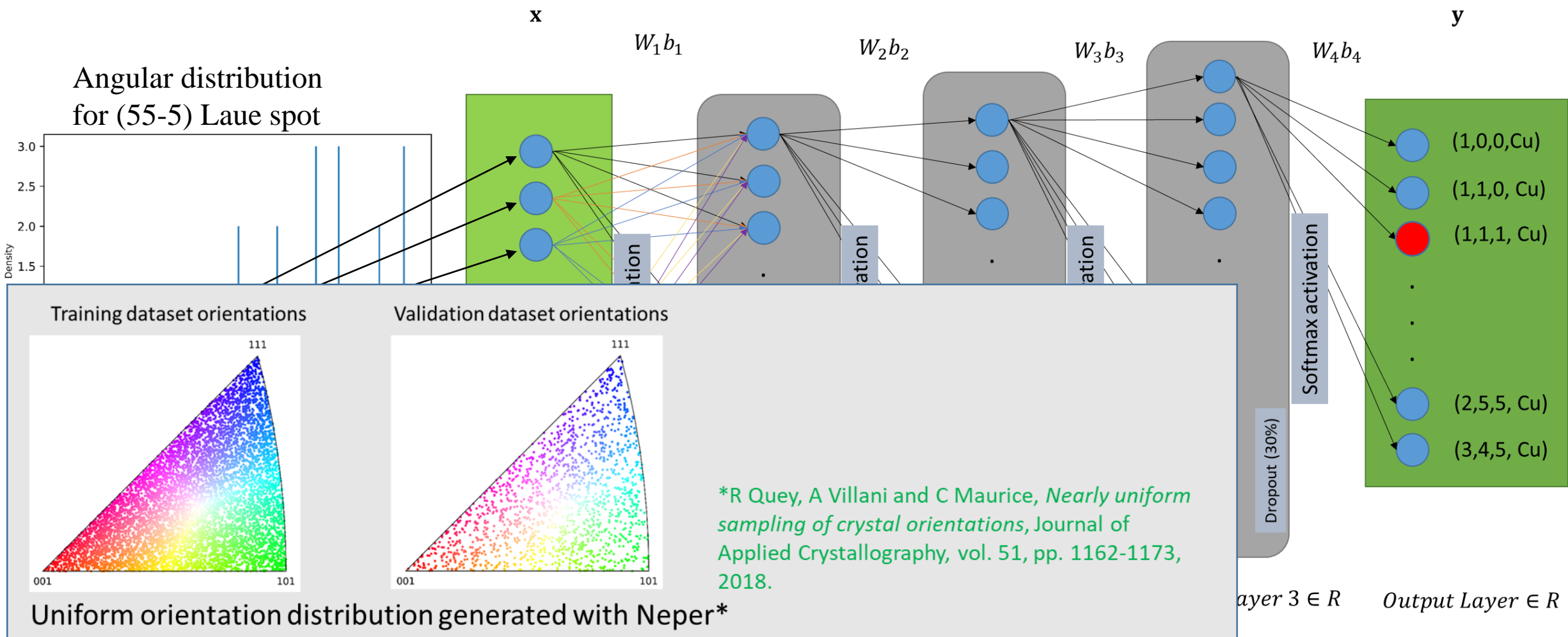
AI-based Laue pattern indexing : an optimized Deep Feed Forward model

A simple NN architecture → Faster prediction



AI-based Laue pattern indexing : an optimized Deep Feed Forward model

A simple NN architecture → Faster **prediction**



➤ Data augmentation: Gaussian noise and disappearance of spots (or partial Laue patterns) based on their energies

AI-based Laue pattern indexing : an optimized Deep Feed Forward model

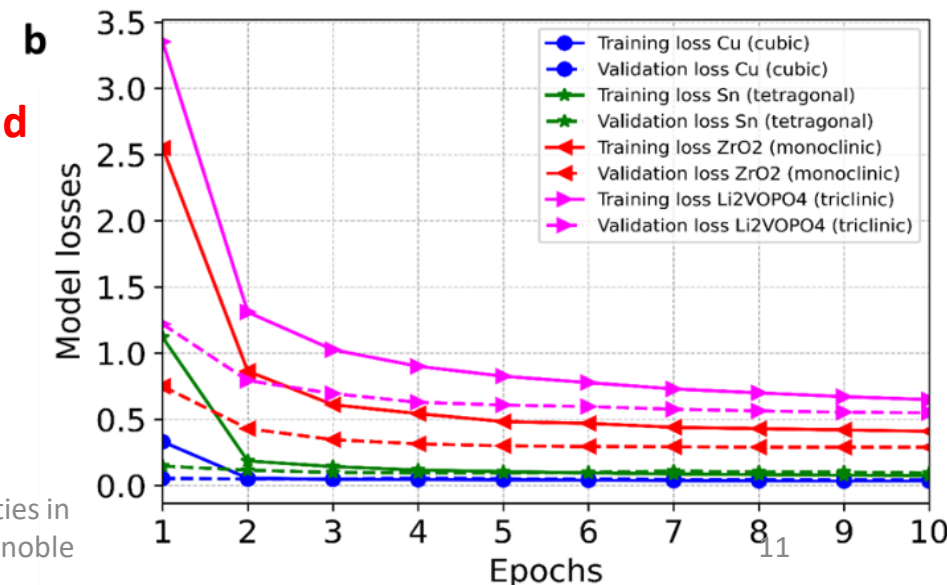
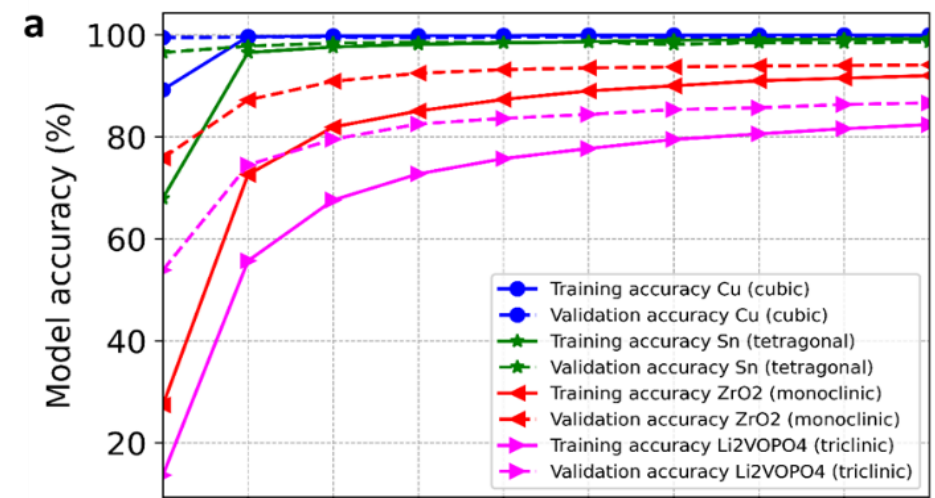
Compound	Crystal system	Model training time (s)	Validation accuracy of the model	Time to predict hcls in one Laue image (s)
Cu	Cubic	25	99.7%	0.25
Ti	Hexagonal	180	98.2%	0.33
Sn	Tetragonal	180	98.6%	0.40
ZrO ₂	Monoclinic	750	94.4%	0.65
Li ₂ VOPO ₄	Triclinic	1200	88.2%	0.86

Training: Standard laptop with 8cores
 Prediction: Single CPU mode

Available Laue tools, LaueNN
 on github

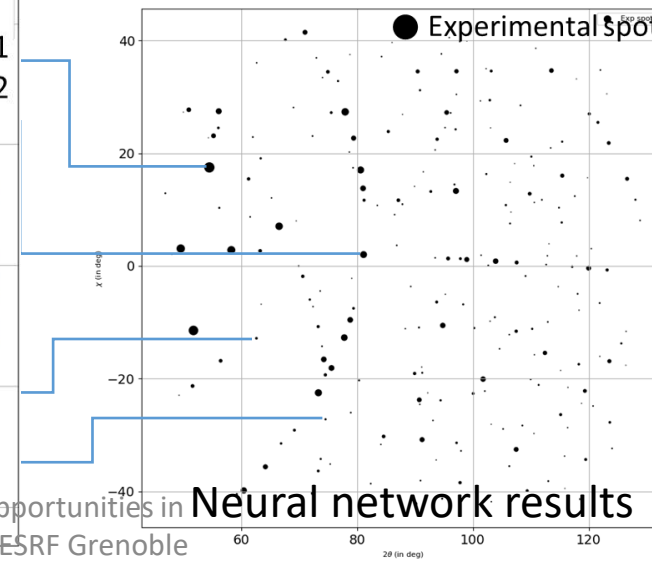
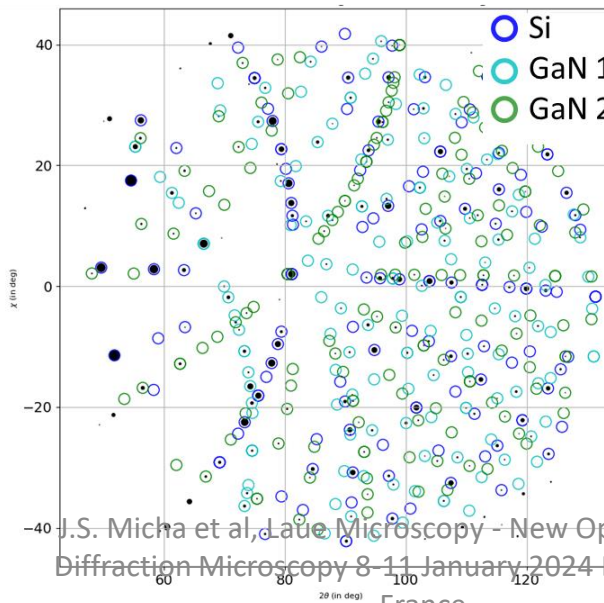
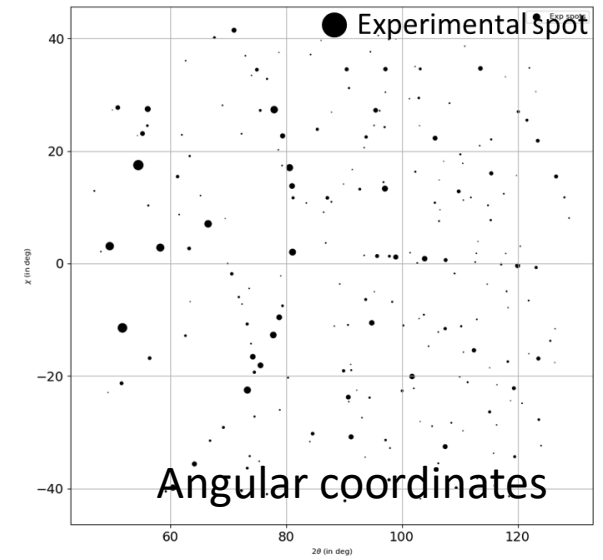
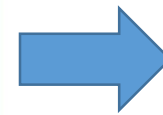
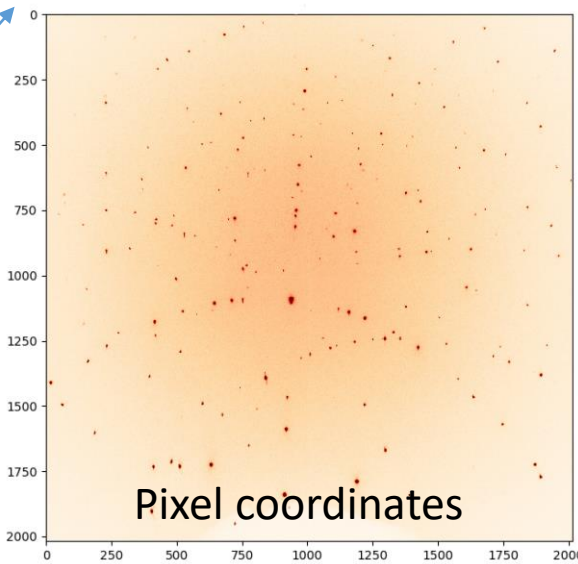
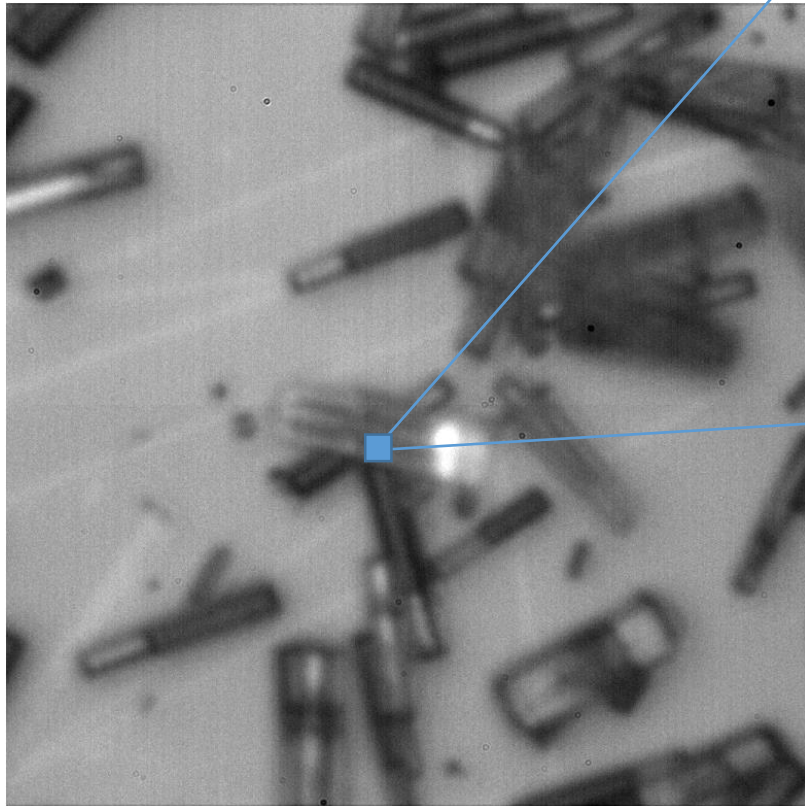
<1 second

➤ Single neural network architecture that works for all crystal symmetries



GaN NWs deposited on Si substrate

Optical microscopy image



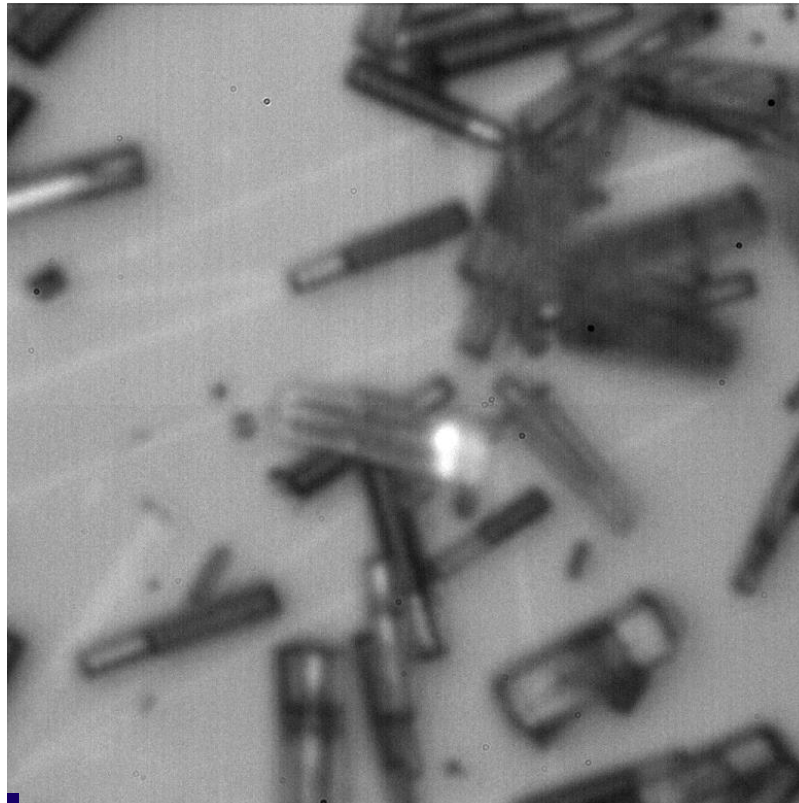
FFNN

Scan direction

Micro-Laue campaign of Joël Eymery
Univ. Grenoble Alpes, CEA, IRIG-MEM, Nanostru
and Synchrotron Radiation Laboratory.

GaN NWs deposited on Si substrate

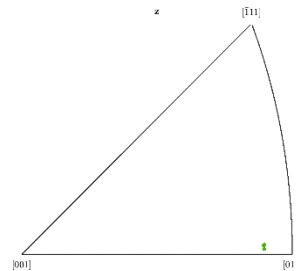
Optical microscopy image



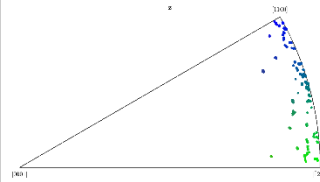
Scan direction



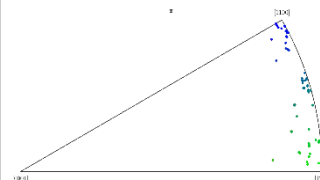
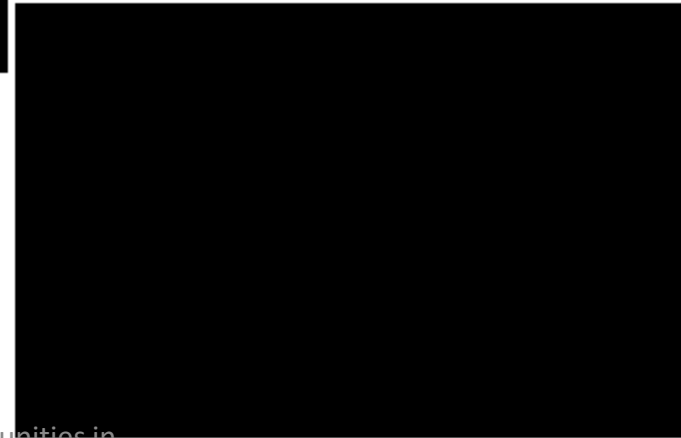
Si- phase



GaN- phase (grain 1)



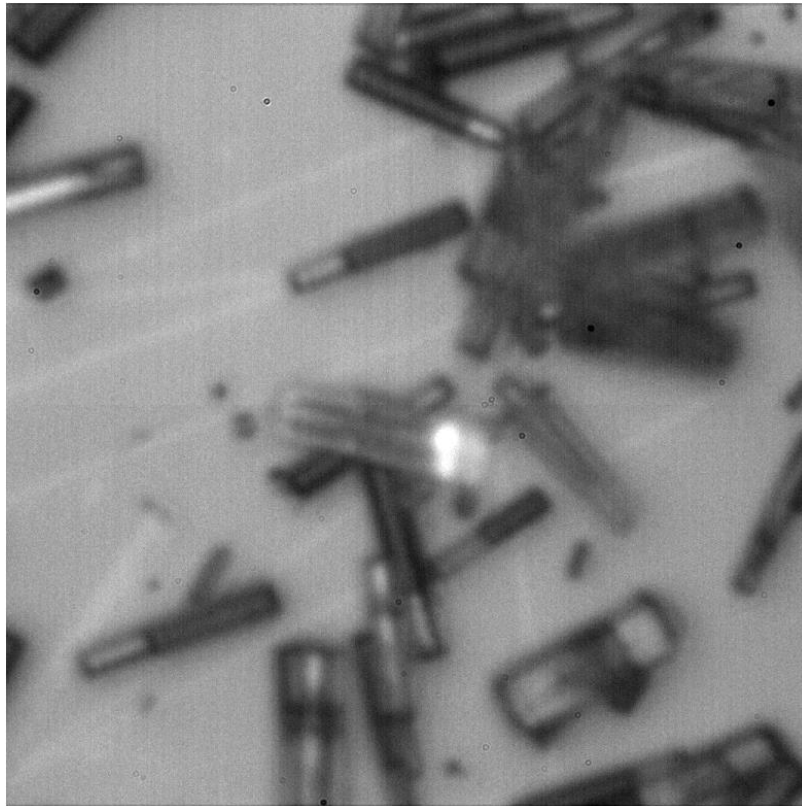
GaN- phase (grain 2)



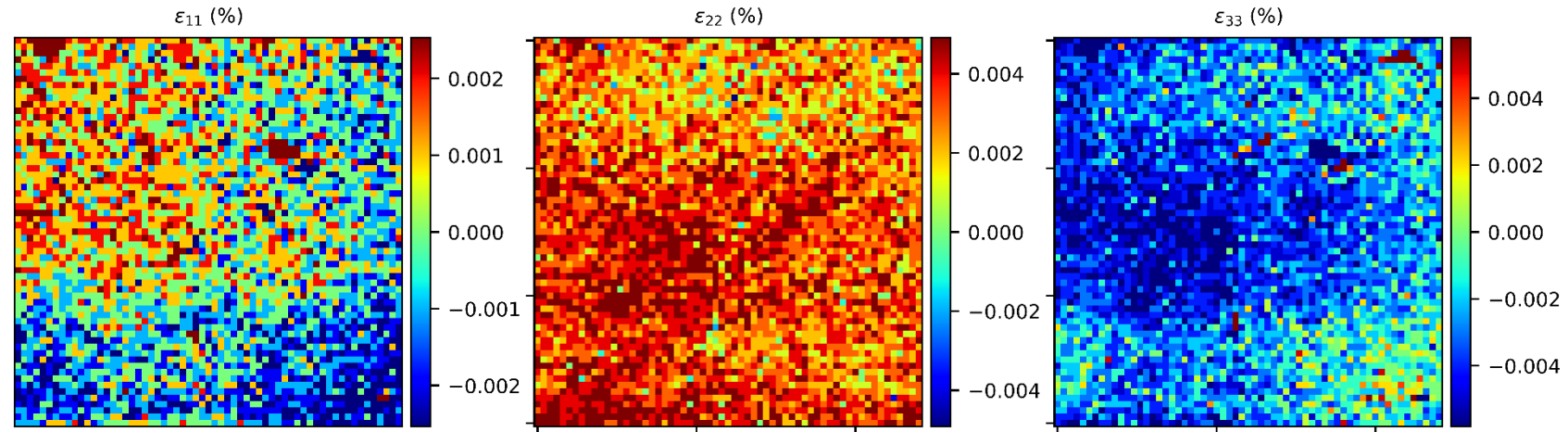
*IPF (Z) plotted with MTEX

GaN NWs deposited on Si substrate

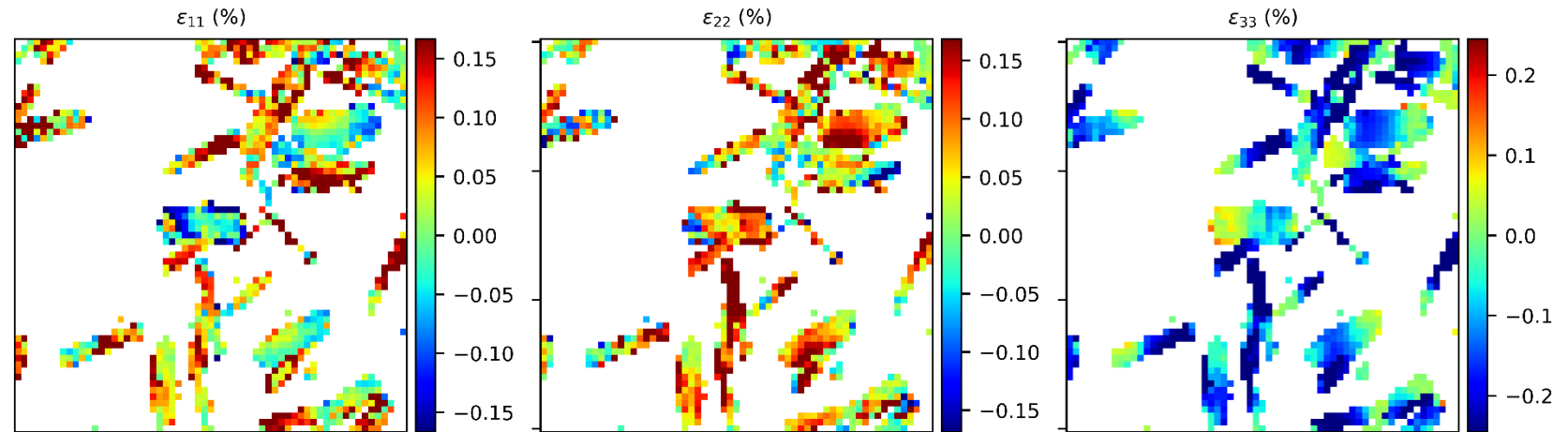
Optical microscopy image



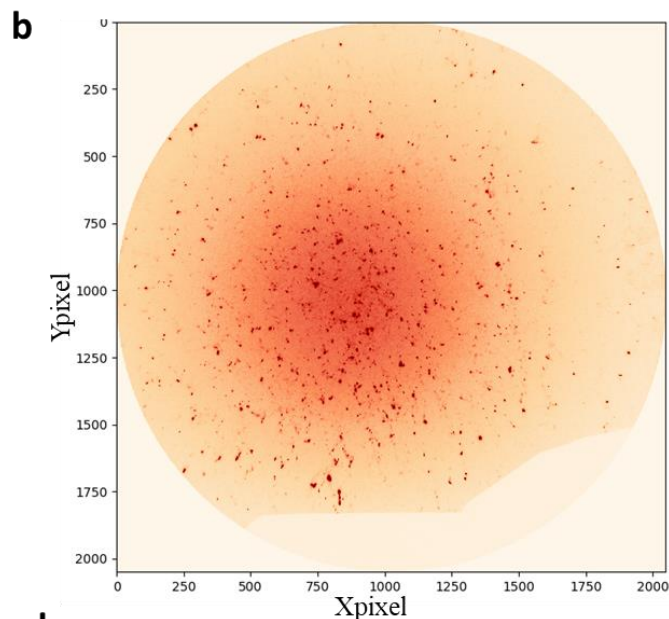
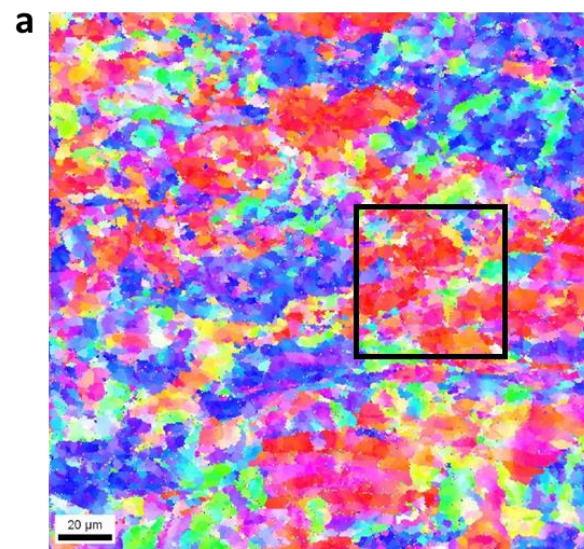
Si- phase



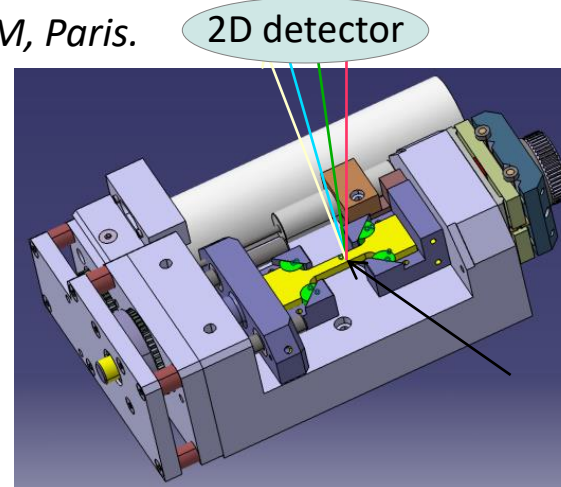
GaN- phase (grain 1)



Polycrystalline Tungsten: validation of strain assessment

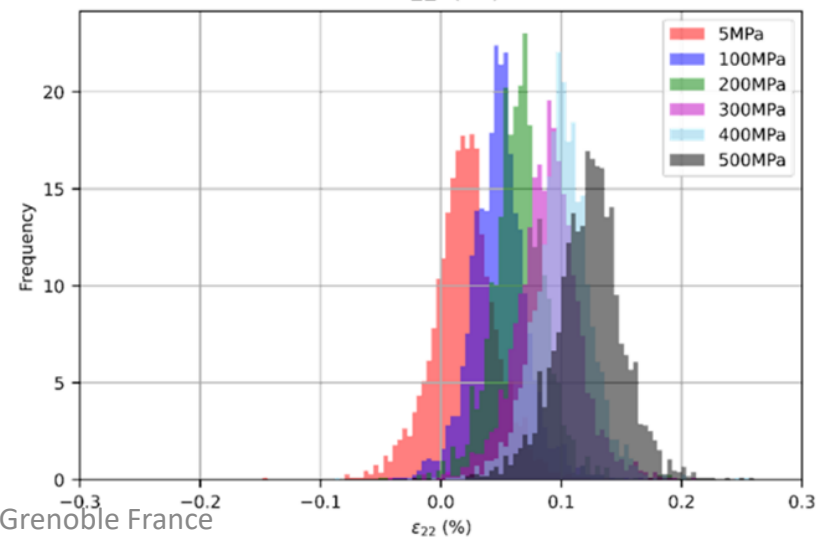
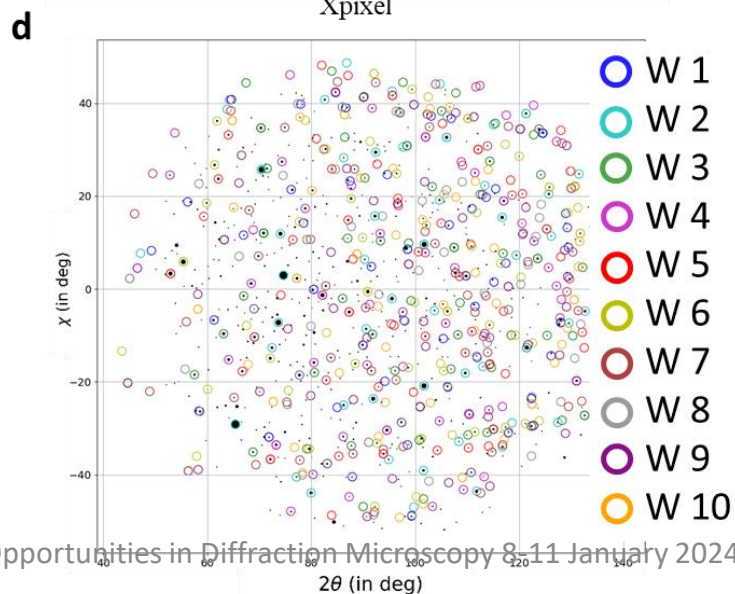
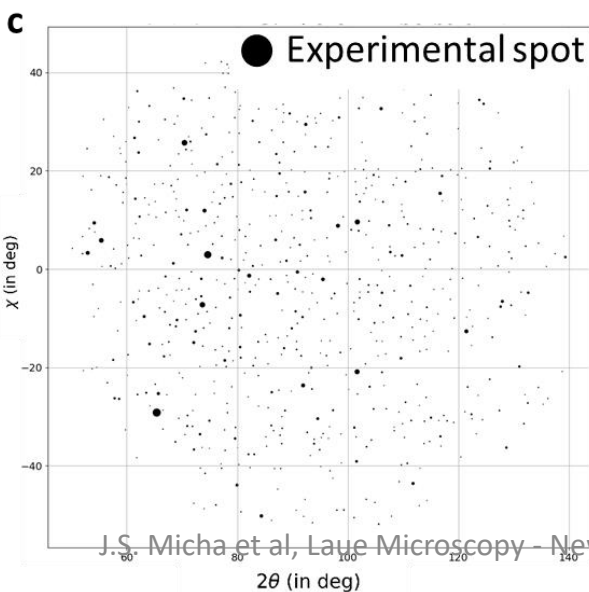


O. CASTELNAU et al
ENSAM ParisTech/PIMM, Paris.



Tensile test

ϵ_{22} (%)



Key step for high resolution: geometry calibration

High strain resolution obtained by a fine calibration of the geometry

⇔ accurate location of point C wrt 2D detector pixels plane array

Use of optical microscope focusing plane

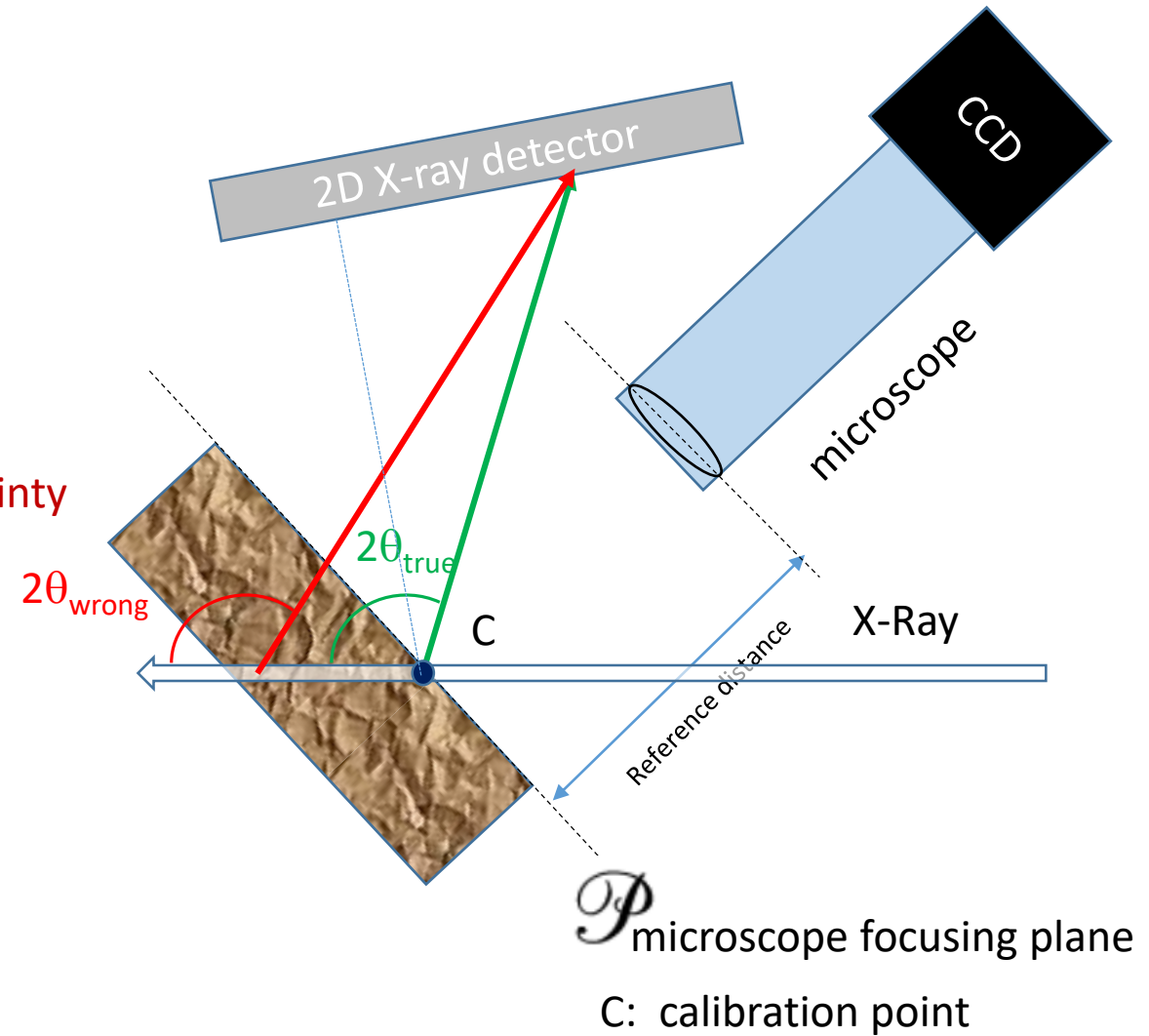
10^{-4} resolution on scattering angles,
absolute strain and absolute lattice parameters
if scattering is close to point C within $10\ \mu\text{m}$ along the beam

Degraded resolution if depth parallax: 10^{-3} for $75\ \mu\text{m}$ depth uncertainty

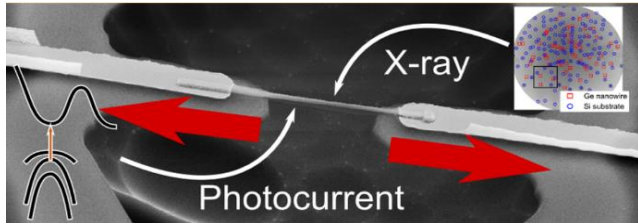
10^{-4} resolution for:

- Objects at surface:
 - High absorbing material
 - Thin films
- Controlled depth of scattering process:
 - Prior knowledge (multilayer, ...)
 - Experimentally determined (3D Laue)

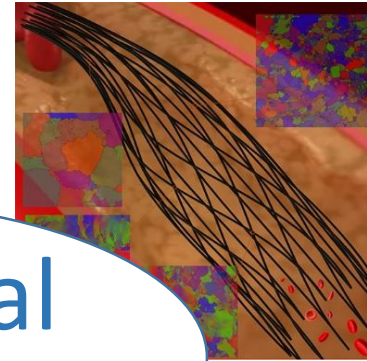
Better resolution on strain gradient than on absolute strain



Applications



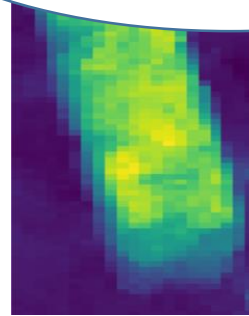
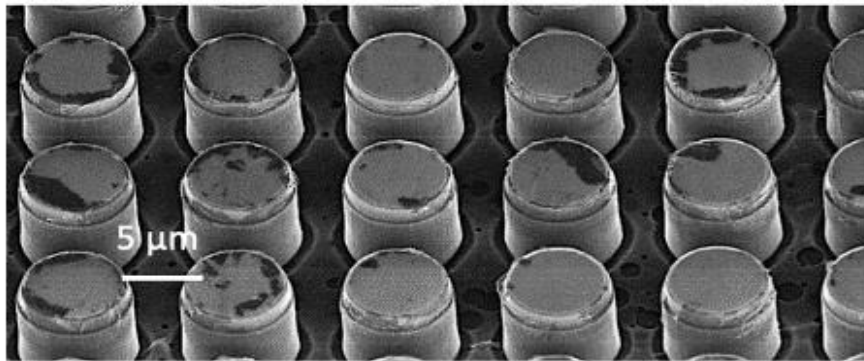
Direct gap strained Ge



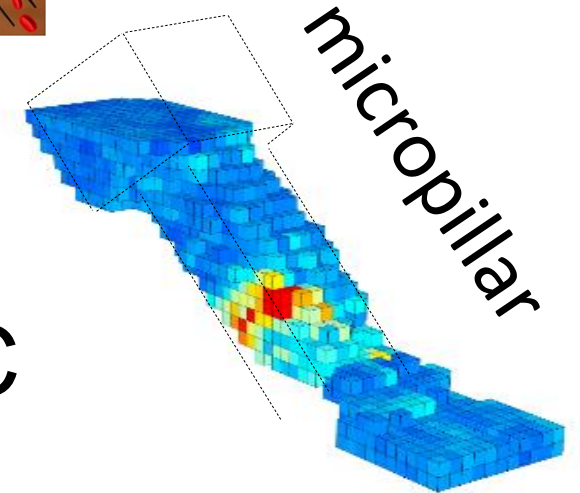
NiTi alloy

InGaN/GaN μ LEDs

Functional materials

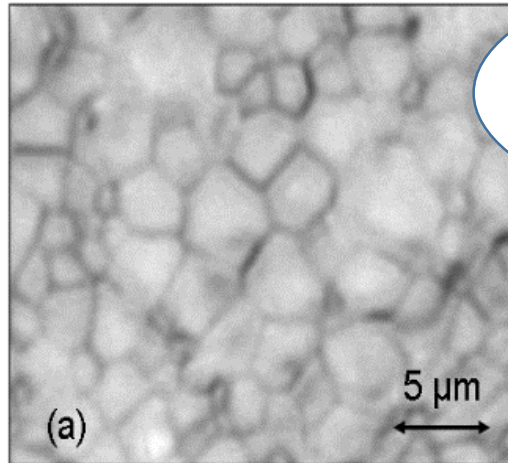


ZrO₂
at 1350 °C



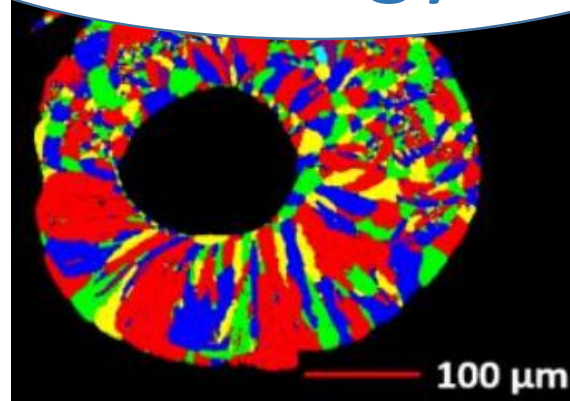
In situ !

Applications

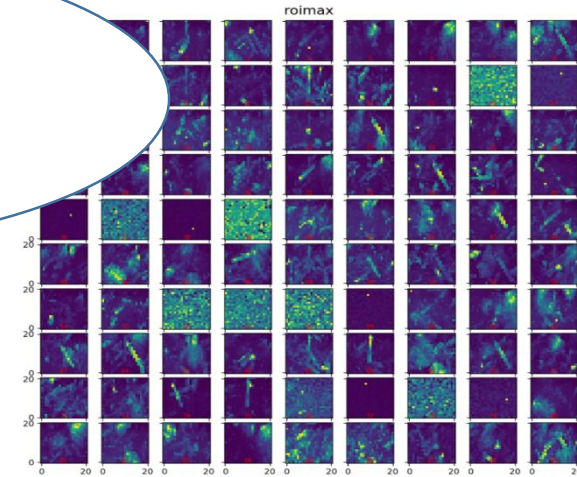


UO₂

Low-carbon energy

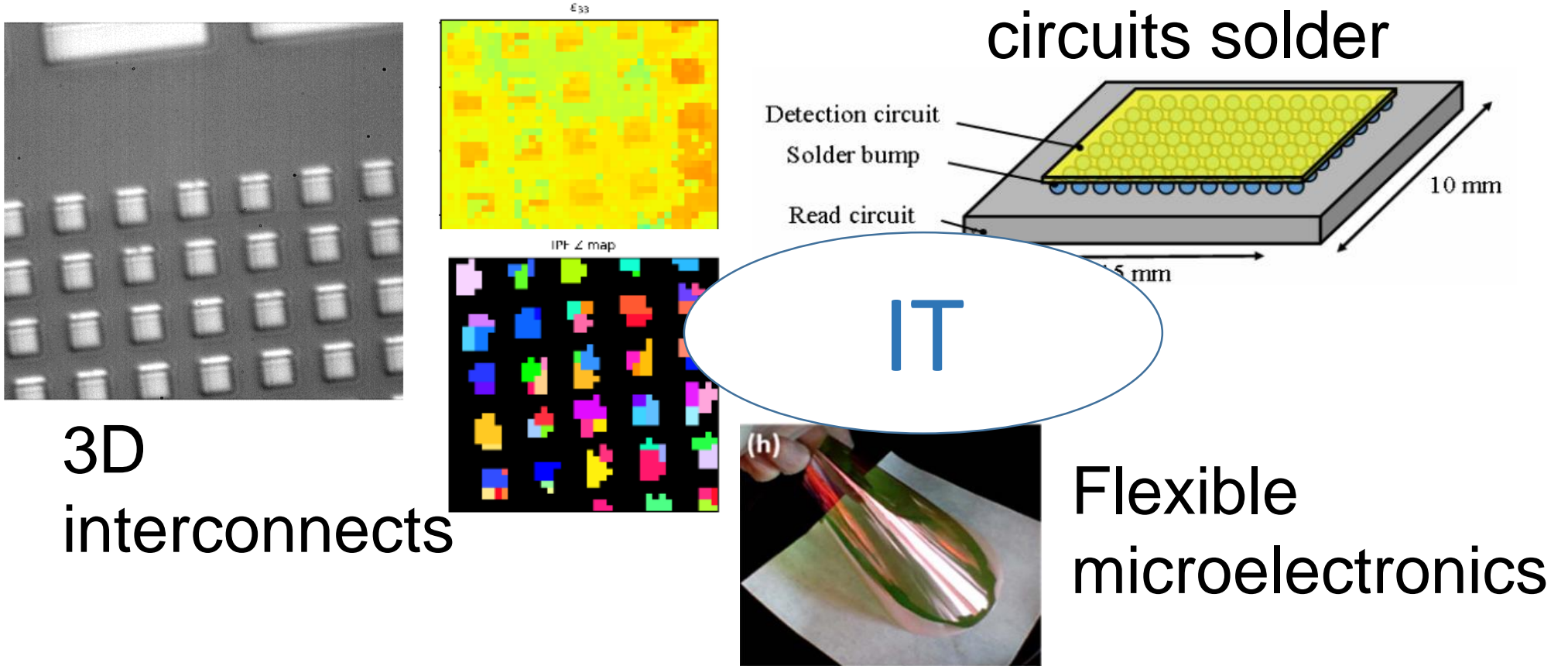


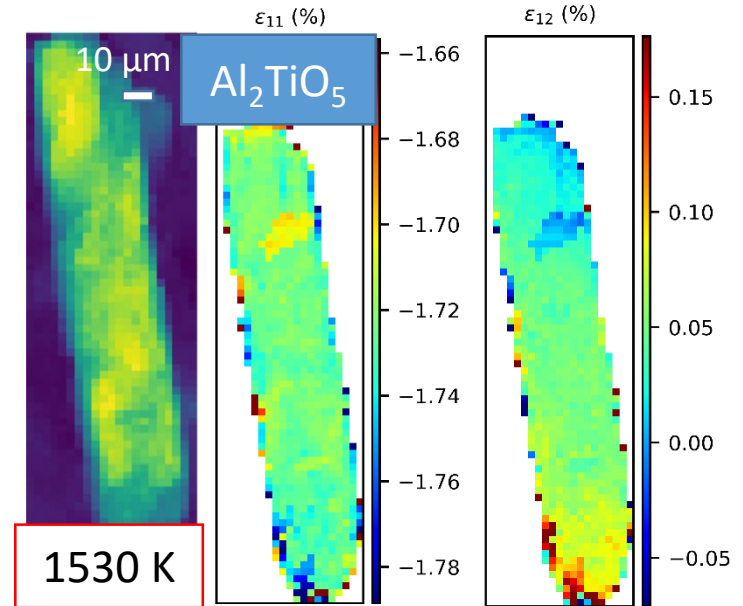
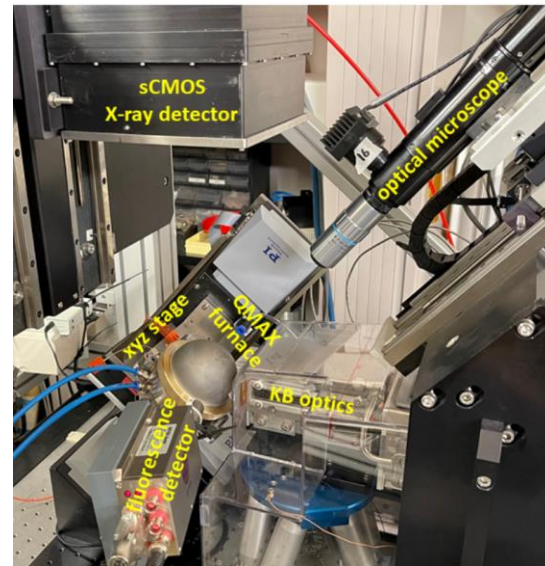
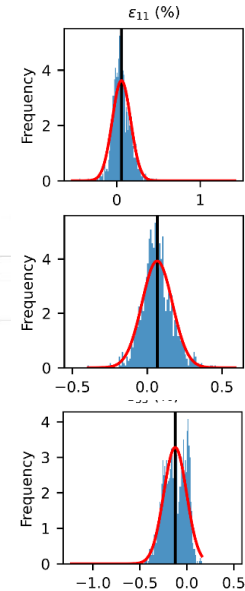
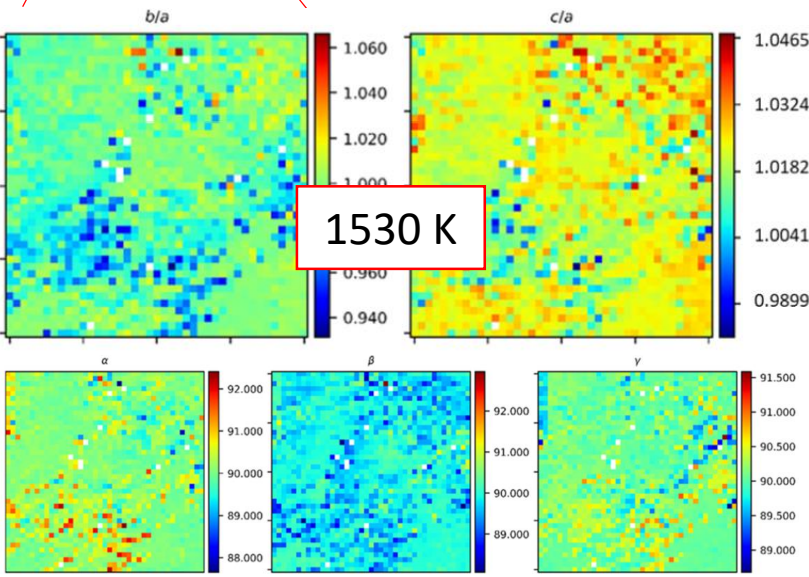
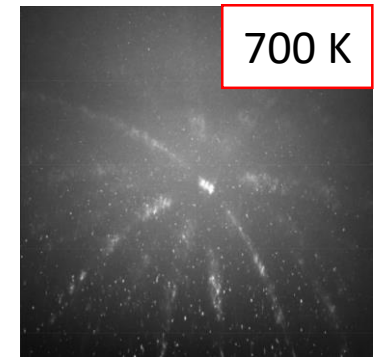
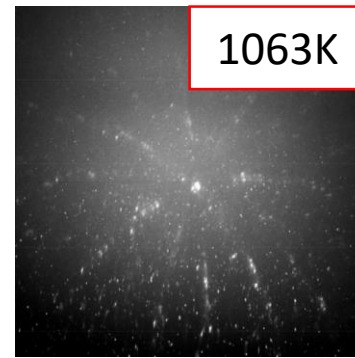
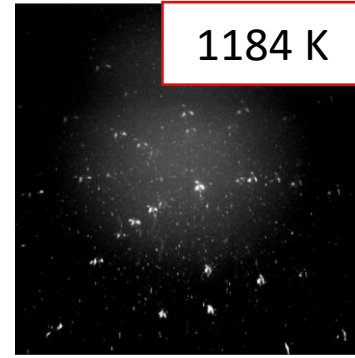
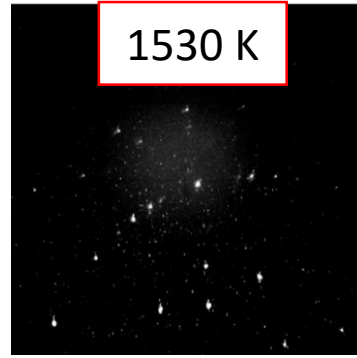
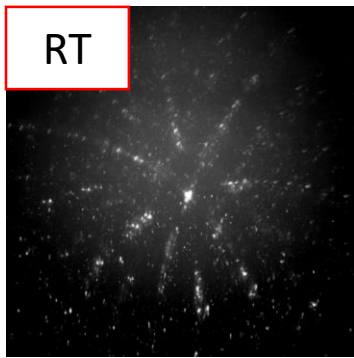
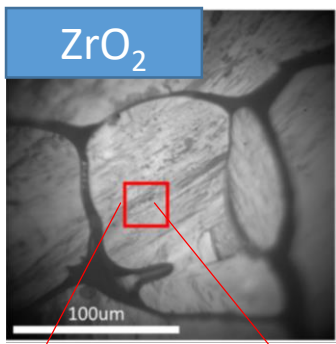
U-Zr-O
(corium)



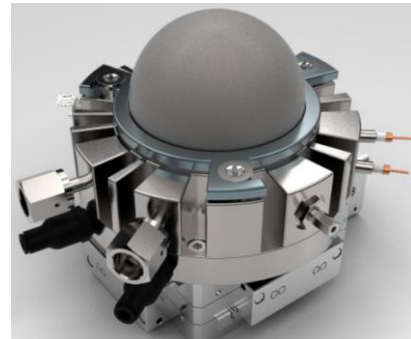
new battery materials

Applications





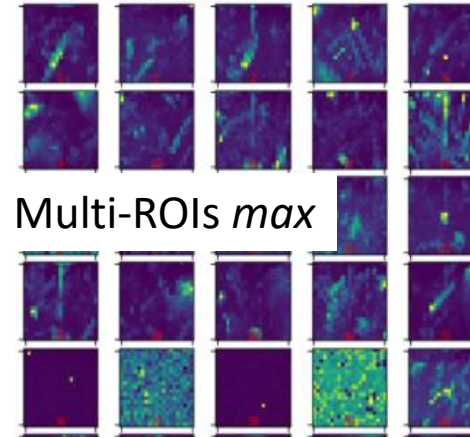
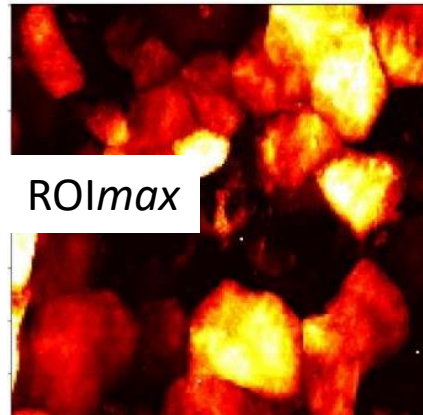
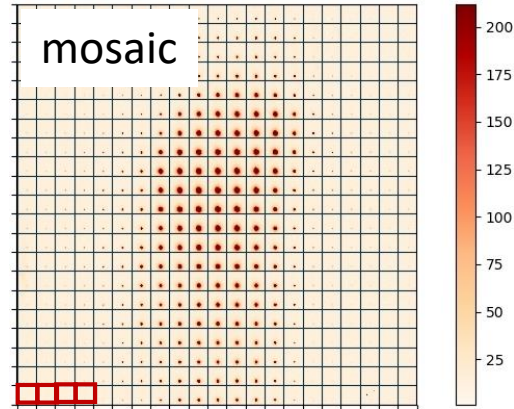
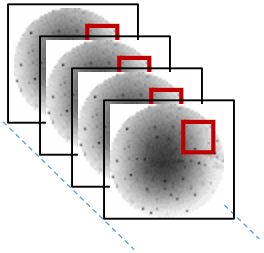
Ceramic paste/Pt heater resistor
50 K/min
PEEK, Be Dome
Air, O₂, vacuum



Collab. R. Guinebretière's group IRCER, Limoges, HotMIX project)

Furnace
R. Guinebretière et al, *J. Appl. Cryst.* (2022)
Experimental premiere >1500K, calibration without microscope
R.R.P. Purushottam Raj Purohit et al, submitted to *J. Appl. Cryst.*
Strain distribution evolution with T
D. Fowan et al, in preparation

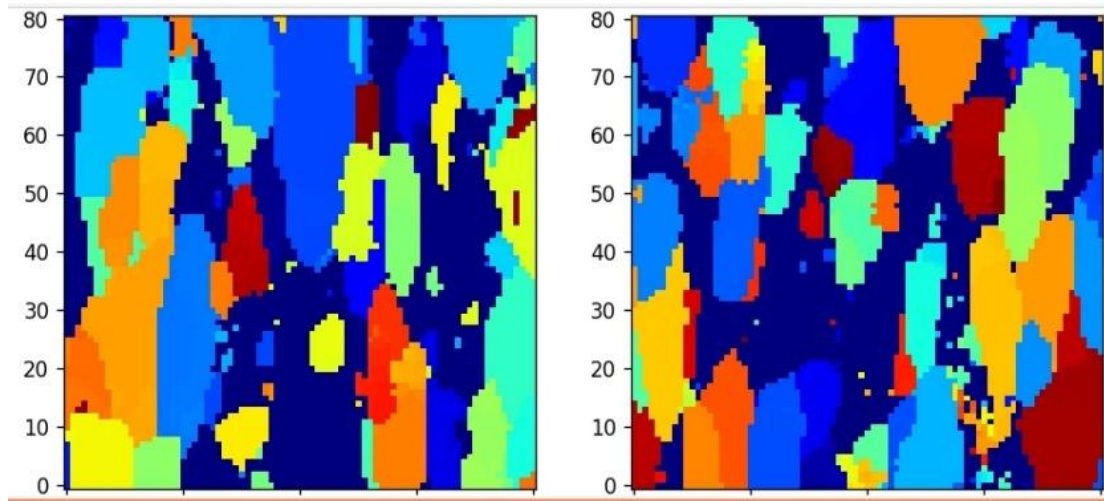
Microscopy Imaging without indexing



Peaks lists dataset
peak existence, correlation,
factorization,...

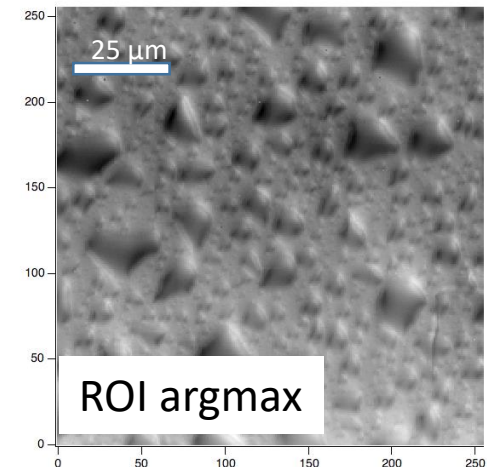
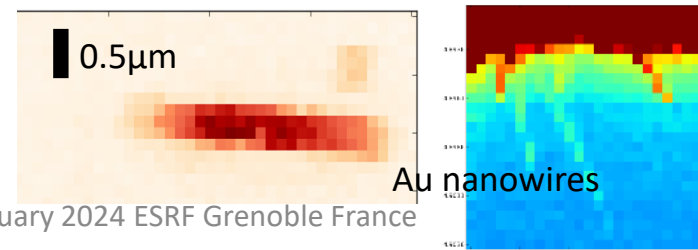
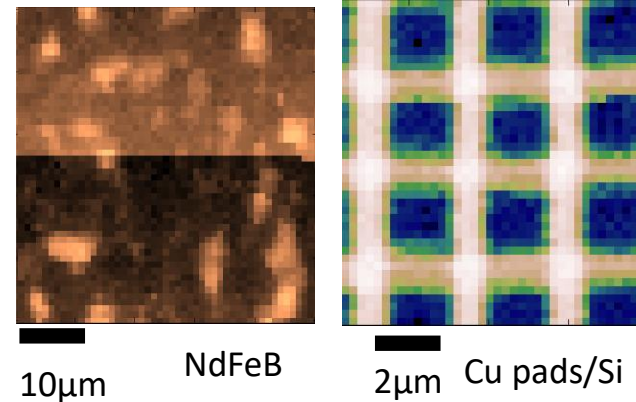


X ray detector: ROI counters
- 2D: Mosaic
- Scalar: max, mean, maxpos

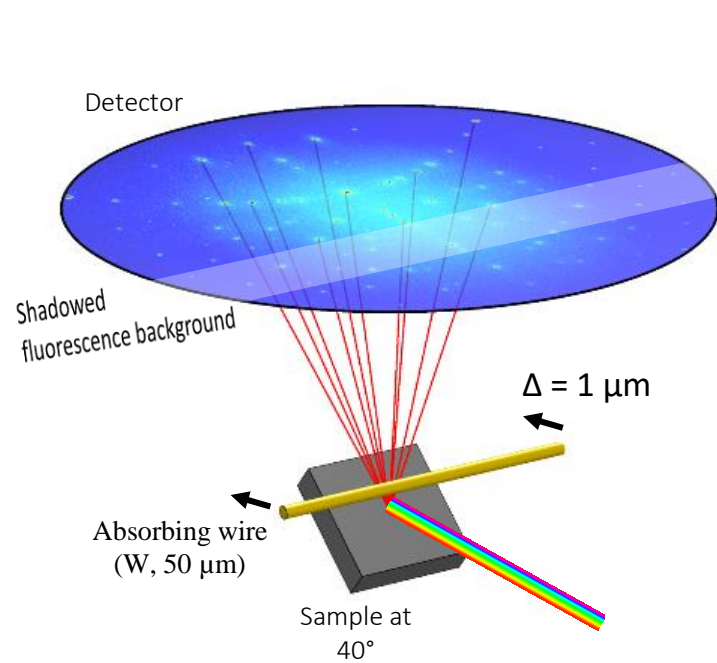


Multi-ROIs maxpos

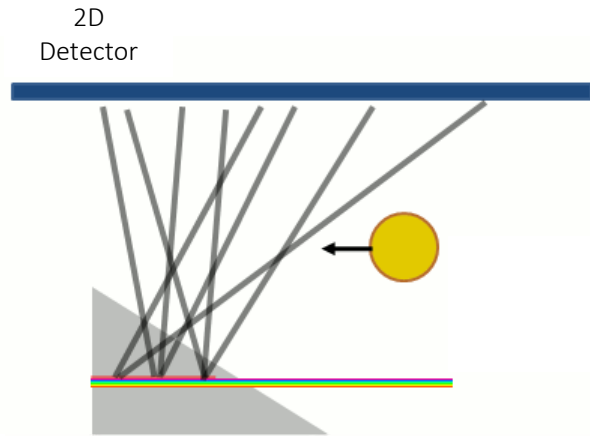
Fluorescence map



3D Laue Microscopy: principles



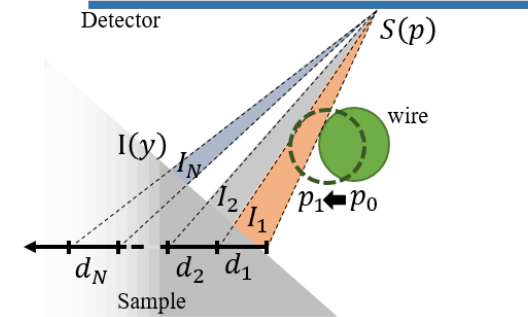
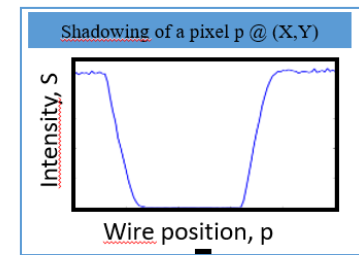
➤ Depth resolution: simple triangulation of the scattered intensity



- Penetration depth from μm to mm
- DAXM
"Differential Aperture X-ray Microscopy"
(Larson et al. 2002)

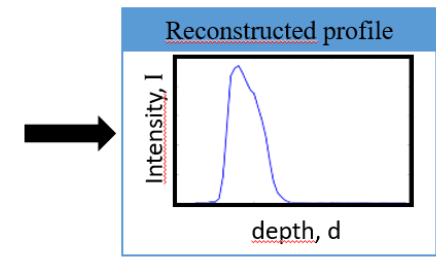
Improvements:

- Transmission function of wire
- 3-5 wires in parallel



$$\begin{aligned}
 S_0 &= I_1 + I_2 + \dots + I_N \\
 S_1 &= F_{11}I_1 + I_2 + \dots + I_N \\
 S_2 &= F_{21}I_1 + F_{22}I_2 + \dots + I_N \\
 &\vdots \\
 S_N &= F_{N1}I_1 + F_{N2}I_2 + \dots + F_{NN}I_N
 \end{aligned}$$

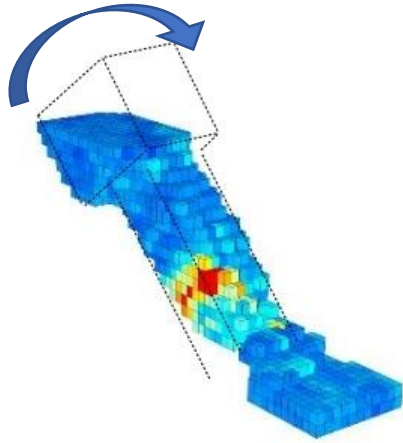
where F_{ij} describe the wire absorption



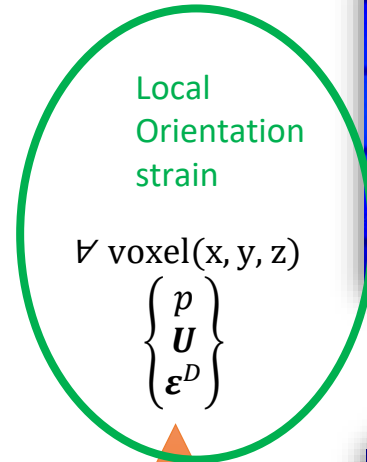
Collab. C. Kirchlechner's group (MPIE, KIT), Germany, XmicroFatigue project

3D- μ Laue : data collection and analysis

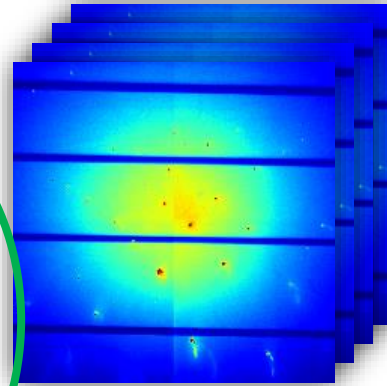
In situ plasticity
fatigue mechanical test
Cu bicrystal



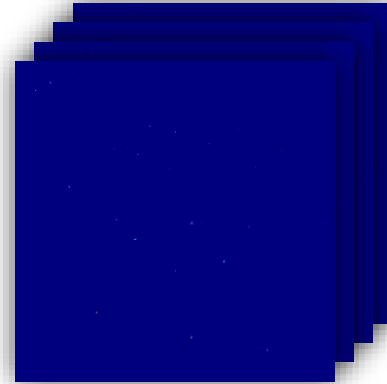
Damage and defects
(dislocations)
Storage and interactions with
surface and grain boundary



3D Scan (x, y, p)

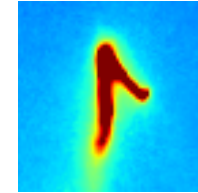


3D map (x, y, z)



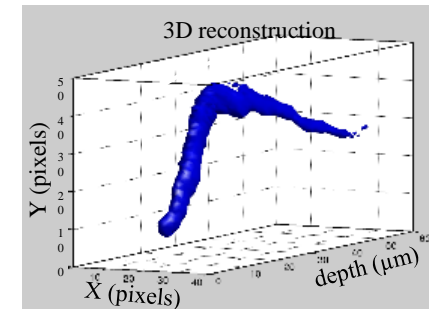
Local Laue pattern p
 \forall voxel(x, y, z)

Segment



✓ New software
package
included in
LaueTools

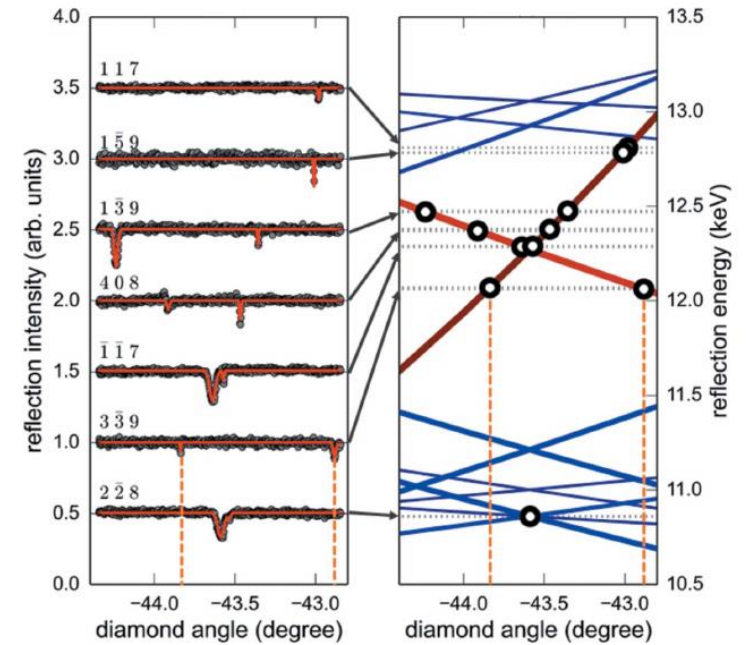
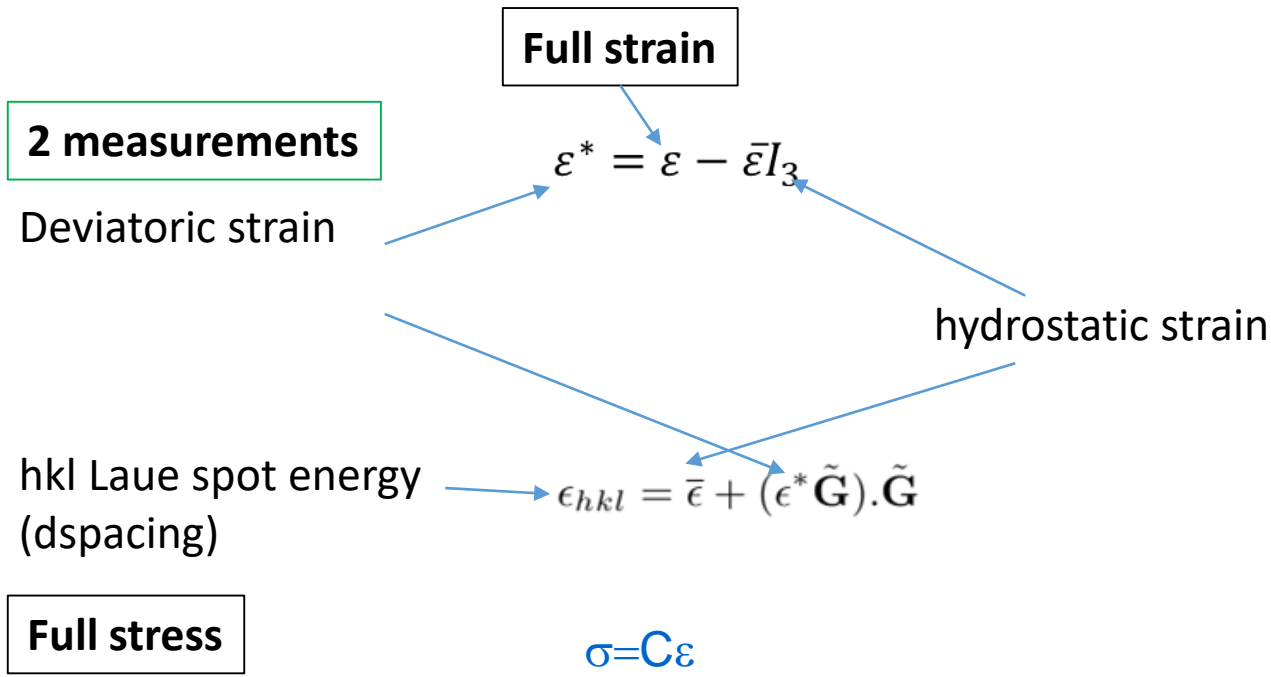
Reconstruct



Assemble

Collab. C. Kirchlechner's group (MPIE, KIT), Germany, XmicroFatigue project

Energy measurements: full strain/stress tensors



Rotating diamond transmission filter

Energy resolution:

Intrinsic HR from crystal diffraction (monochromator, crystal analyser): **some 10^{-4}**

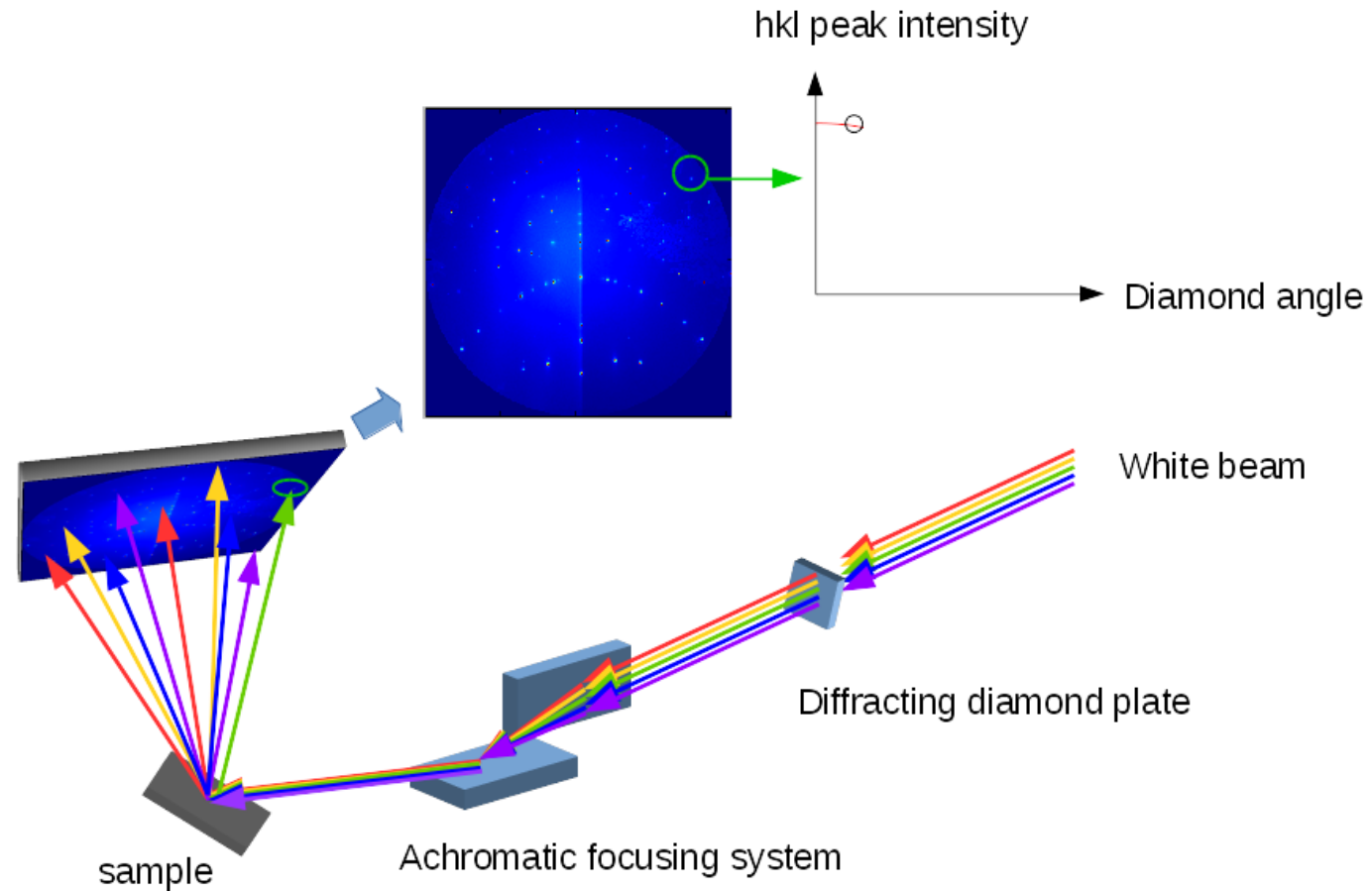
Much Less resolution for solid state detector (punctual SDD, 2D pnCCD): $\sim 10^{-2}$ (broadening)

$< 10^{-3}$ (average energy distribution)

HR from dev. Strain by assuming $\sigma_{zz} = 0$ (at surface). **Suited for Thin film 2D map**

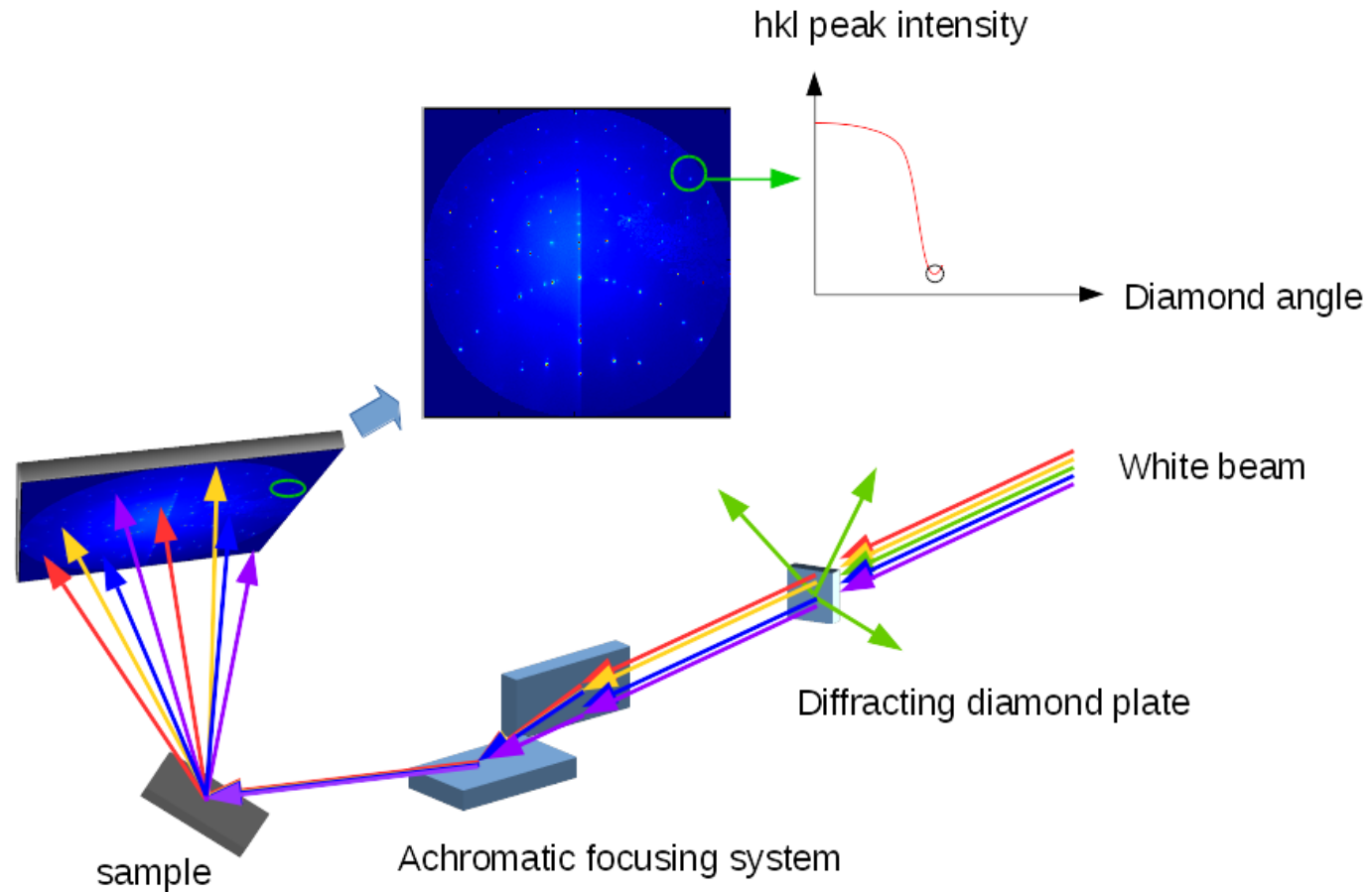
μ Laue Diffraction | energy fine measurements using rotating transmission diamond filter | Full Stress

"Inverse" monochromatic diffraction The Rainbow filter technique



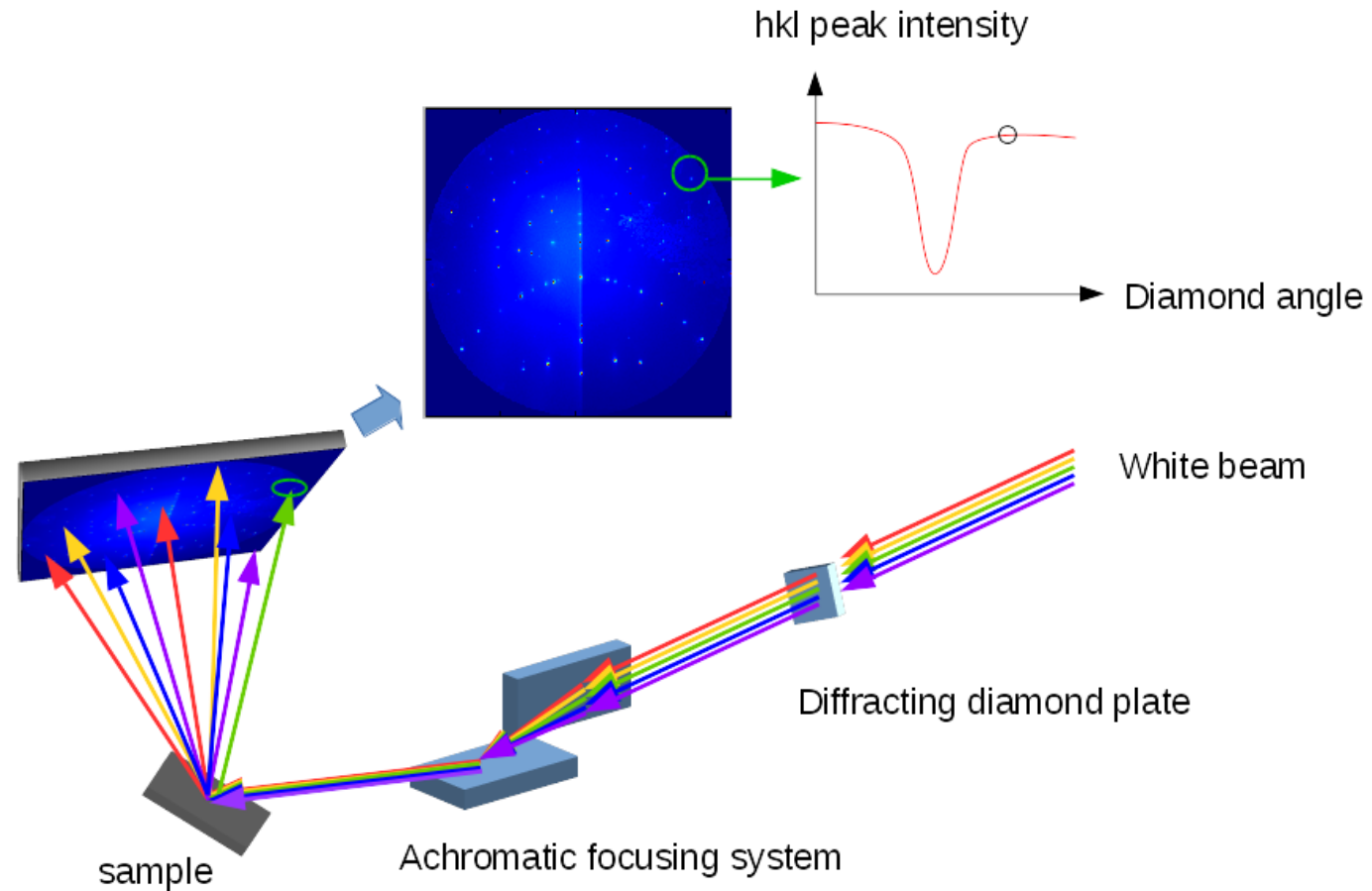
μ Laue Diffraction | energy fine measurements using rotating transmission diamond filter | Full Stress

"Inverse" monochromatic diffraction The Rainbow filter technique



μ Laue Diffraction | energy fine measurements using rotating transmission diamond filter | Full Stress

"Inverse" monochromatic diffraction The Rainbow filter technique



Conclusions μ Laue @ ESRF

Microstructure and Metrology characterisation tool

- ✓ **Open to broad scientific community**
- ✓ High angular resolution
- ✓ Few 100s nm spatial resolution
- ✓ *In situ* experiments (elasticity – plasticity), signal with large strain
- ✓ Addons mapping measurements: 3D, full strain/stress, element concentration

Next proposals call: March 2023

Contact | infos | free tests

micha@esrf.fr

Current & future challenges

- ✓ **LaueMAX Upgraded instrument (flux X 10, beamsizes 150 nm) coming soon Spring 2024**
- ✓ use of AI assistance (DIADEM project):
 - data collection (detect and select high quality data)
 - data analysis (peaks overlap, peaks subgrains splitting)

Crowded Laue patterns
(multiple grains, twins)
Peak Shape analysis
(Defects)
Infer topography
(depth, GB, 3D shape)

